

H22S75 Chip Datasheet

SUMMARY DESCRIPTION

The H22S75 is an integrated system-on-a-chip (SoC) platform that targets drones (flying cameras), action cameras, and other high-performance video applications.

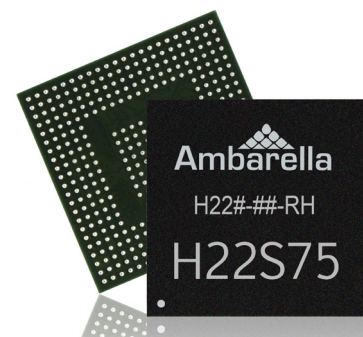
H22S75 chip provides a quad-core 1 GHz ARM Cortex-A53 CPU for custom applications, a high-performance digital signal processing (DSP) sub-system with an image sensor pipeline (ISP), and high-performance H.265 / HEVC and H.264 / AVC encoders capable of simultaneous video recording and streaming.

KEY FEATURES

- Embedded ARM quad-core Cortex-A53 1 GHz CPU with L2 cache
- Electronic Image Stabilization (EIS) with 6-axis correction (translational, pitch, yaw, and roll) and rolling shutter correction for drones and action cameras up to 4Kp30
- Advanced dynamic range (WDR and HDR) engine up to 4Kp30
- Dual sensor input and dual processing pipeline
- 3D motion-compensated noise reduction (MCTF)
- H.265 / H.264 encode performance up to 4KP30
- Simultaneous streaming of H.265 and H.264 encoded streams
- 369-pin, 0.65-mm pitch WFBGA package (14 mm x 14 mm)
- 14-nm CMOS Low Power (LP) technology
- Operating temperature from -20 °C to +85 °C

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1. OVERVIEW

This preliminary datasheet for the H22S75 processor from Ambarella begins with a brief introduction to the chip ([Section 1.1](#)) and a summary of key features ([Section 1.2](#)). Chapter 2 describes the H22S75 peripheral interfaces. For pin details and electrical characteristics refer to Chapter 3 and Chapter 4, respectively. See Chapter 5 for package information and Chapter 6 for Ambarella contact and ordering details.

Please note that the chip features described in this datasheet are subject to change. Details that have not been entirely finalized (e.g., encoding specifics) are provided using conservative estimates (i.e., final encoding performance is expected to meet or exceed the estimate provided). Please contact an Ambarella representative for additional information.

1.1 Introduction

The H22S75 is an integrated SoC platform that targets high-definition and ultra high-definition cameras with performance up to 4KP30. H22S75 chips provide a quad-core Cortex-A53 ARM CPU for custom applications, a digital signal processing (DSP) subsystem with an image sensor pipeline (ISP), and a high-performance H.265 / HEVC and H.264 / AVC encoding engine capable of simultaneous streaming. A functional block diagram of the H22S75 SoC is provided below.

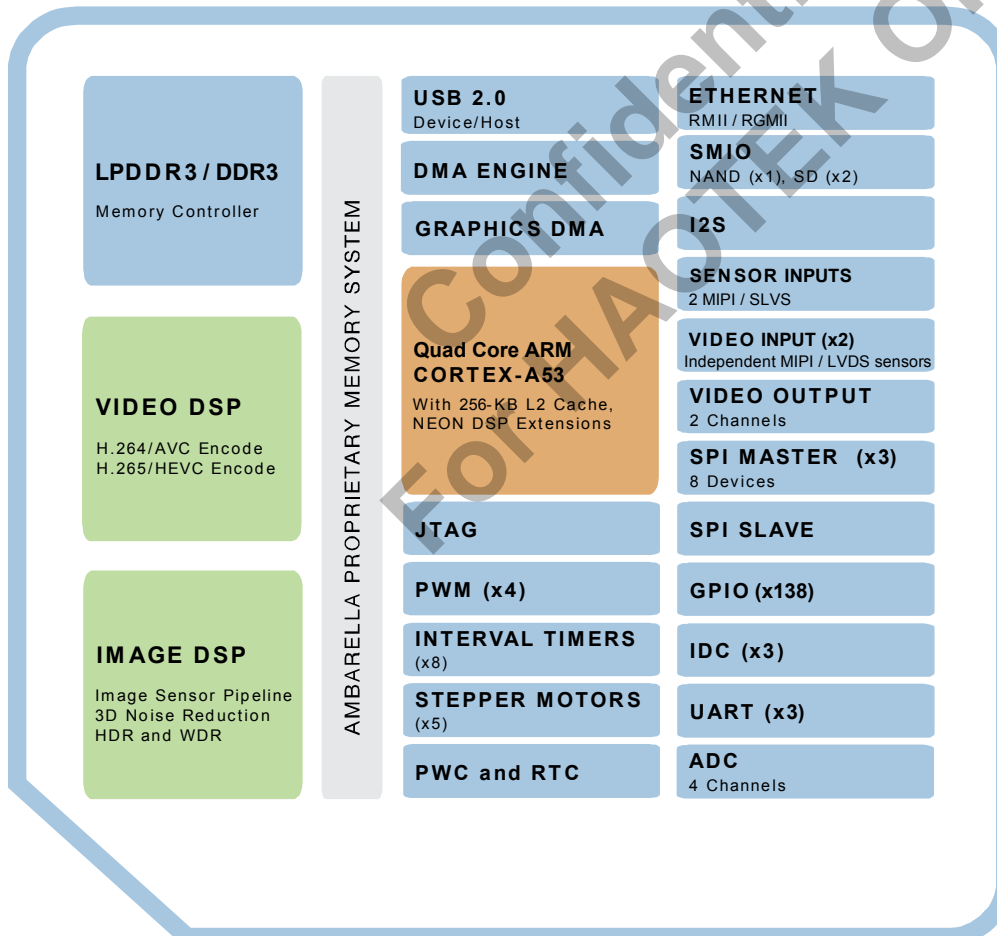


Figure 1-1. H22S75 Overview: Functional Block Diagram of the H22S75 SoC.

The H22S75 SoC provides a glueless interface to Serial sub-LVDS, SLVS, HiSPi, and MIPI interfaces, as well as parallel connections to popular CMOS image sensors. The ISP offers advanced image-processing features including improved multi-exposure high dynamic range (HDR) processing, wide dynamic range (WDR) single-exposure tone mapping with local contrast enhancement, 3D motion-compensated noise reduction (MCTF), edge enhancement, 3A, electronic image stabilization (EIS) and dewarping.

The H.264/H.265 codec engine delivers versatile encoding up to 4KP30 total performance, including simultaneous encode streams. The high-efficiency encoder implements full-function H.265/HEVC and H.264/AVC video encoding for the highest-quality and lowest possible bitrate. These functions include bidirectional prediction (B-frames), large motion-estimation search range, and macroblock-level quantization. Ambarella builds in flexibility with a multi-streaming function, allowing on-the-fly start/stop as well as the adjustment of the bitrate, frame rate, and GOP of each individual stream.

A 1 GHz quad-core ARM Cortex-A53 CPU with NEON DSP extensions and floating point support is available for implementing full-featured user applications.

The H22S75 chip is fabricated using low-power 14-nm CMOS technology and integrates advanced power-saving modes, such as utilizing DSP-subsystem memory resources to reduce external memory bandwidth and total camera system power requirements.

1.2 Feature List

Features of the H22S75 chip include:

- Embedded quad-core ARM Cortex-A53 CPU
 - Clock frequency up to 1 GHz
 - 32-KByte data / 32-KByte instruction cache
 - 256-KByte L2 cache
 - NEON SIMD acceleration
- DDR3 and LPDDR3 controller
 - Up to 1 GHz clock rate
 - 32-bit wide data bus
 - Maximum capacity of 16 Gbits (2 GByte)
- Image pipeline
 - More than 800 MPixel/s input pixel rate
 - Fish-eye lens dewarping and barrel distortion correction
 - 3D Electronic Image Stabilization (EIS) with 6-axis correction (translational, pitch, yaw, and roll) and rolling shutter correction
 - Black level correction
 - Dynamic and static defect pixel cluster correction
 - RGB Bayer demosaicing
 - Lens shading correction
 - 3D LUT color transform with gamma

- Advanced motion-compensated sharpening
- Advanced dynamic range (WDR and HDR) engine with multi-exposure fusion and motion artifact reduction
- 3D noise reduction (Motion Compensated Temporal Filter, or MCTF)
- Adjustable 3A; exposure, white balance and focus control (AE/AWB/AF)
- RGB and YUV statistics, histogram and AF focus value generation
- Luma sharpen and chroma noise filter
- Crop, mirror, flip, 90°/270° rotation
- Alpha-blending OSD up to full-frame overlay for text, image and privacy mask
- Flexible APIs and image-tuning tools
- Video engine
 - H.265/HEVC Main Profile Level 5.1 encoding
 - H.264 MP/HP Level 5.1 encoding
 - JPEG encoding
 - Maximum encode performance:
 - Main stream:
 - 4Kp30
 - 1920x1080p120
 - 1280x720p240
 - Secondary stream up to 1080p30 (the performance is based on a combination of overall system load and features)
 - Advanced compression tools
 - I, IP, IBP modes (M=1,2,3,4...; IP, IBP, IBBP, IBBBP...)
 - B-frames and hierarchical GOP
 - Up to three reference frames
 - Flexible rate control
 - CBR, VBR and Constant QP with max bitrate control
 - Macroblock-level adaptive quantization
 - Bitrate control ranging from 16 kbit/s to 50 Mbit/s
 - Frame rate ranging from 1/16 fps to 120 fps
 - Dynamic ROI encoding per frame with up to 32 free-form areas at macroblock boundary
- Sensor/Video Input (VIN) interfaces
 - Two input channels with multiple input modes
 - Primary channel supports up to 8-lane sub-LVDS / SLVS / HiSPi input or up to 4-lane MIPI input
 - Secondary channel supports up to 4-lane SLVS / HiSPi / MIPI input
 - The primary and secondary input channels may be combined to support a single 10-lane SLVS / HiSPi sensor

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- Support for 14-bit parallel and LVCMOS sensors
- Support for popular CMOS sensors: Sony, ON Semiconductor (Aptina), Panasonic, OmniVision, and others
- Two clocking options (PLL-generated gclk_vin or SLVS bit clock)
- 16-bit CCIR.601 video input with external sync signals
- 8-bit, 10-bit, 12-bit or 14-bit BT.656-style video input with embedded sync codes including full-data-range support
- Video Output (VOUT) interfaces
 - Two logical channels to drive three video output ports
 - One logical channel drives HDMI or analog
 - One logical channel drives digital
 - Support for RGBA and YUVA OSD
 - Video DAC for 480i/576i composite PAL/NTSC output
 - HDMI 2.0 output with Consumer Electronics Control (CEC) and on-chip PHY
- AHB Bus DMA controller
 - Memory-to-memory transfers including support for transfers between memory and peripherals
 - Programmable transfer count up to 4 MB
 - DMA scatter/gather via chained descriptor list in memory with DMA control information source
- Dedicated DMA co-processor for graphics and image operations
 - Offers linear copy, 2-D copy, composite, and alpha-blend image operations
 - Supports 4- to 32-bit pixel formats
- I2S digital audio interface (stereo)
 - Audio record/playback
- Ethernet MAC controller
 - IEEE 802.3 compliant with full- and half-duplex (IEEE 802.3x flow-control) and Jumbo frames
 - IEEE 802.1Q VLAN tag detection
 - Checksum off-load for received IP and TCP/UDP packets
 - Dedicated pins for RMII or MII interface
 - FIFO (2 KB / 2 KB) and DMA support
- USB 2.0 interface
 - One port configurable as host or device, with built-in PHY
- Flexible Storage Media Input / Output (SMIO) interface
 - NAND Flash controller
 - Up to 8-Gbit device, 512-Byte and 2-KByte page sizes
 - 8-bit flash chip data bus
 - 4-bit and 8-bit SLC with ECC hardware and read-confirm support

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- BCH error correction and increased spare area available
- Two SD controllers (SD0, SD1)
 - SD0:
 - SDIO v3.0, SD, SDHC, SDXC, MMC and eMMC operation with boot support and UHS-I speed
 - Support for 1-bit, 4-bit, and 8-bit SD mode
 - SD1:
 - SDIO v2.0, SD, SDHC, SDXC, MMC and eMMC operation
 - Support for 1-bit, 4-bit, and 8-bit SD mode
 - 32-GByte maximum capacity for SDHC SD Card
 - 2-TByte maximum capacity for SDXC SD Card
 - CRC7 for command and CRC16 for data integrity
- Multiple boot options
 - NOR-SPI, NAND Flash, USB and eMMC
- Generic interrupt controller including GIC CPU-offload functionality
- SSI / SPI controller interfaces
 - Two SSI / SPI masters with DMA support for up to eight device enables
 - One dedicated SSI / SPI slave port to connect to an external system master
- Two-wire serial Inter-Integrated Circuit (I2C / IDC) interfaces (x3)
 - Configurable IDC buses
- UART interfaces (x3)
 - DMA support
 - One interface supports flow control
- Up to 138 General Purpose Input/Output (GPIO) pins with individual pull-up/down control
- ADC (three channels) with high/low threshold interrupt generation and 12-bit resolution
- Built-in power controller for power-up/down sequencing
- Real Time Clock (RTC)
- Interval timing with eight general-purpose timers configurable as external event counters
- Watchdog timer
- Stepper motor interface (five channels) with four-channel Micro-Stepper interface
- Pulse Width Modulators (PWM) (x4)
- JTAG In-Circuit Emulator (ICE) interface for debugging
- 369-pin, 0.65-mm pitch WFBGA package (14 mm x 14 mm)
- 14-nm CMOS Low Power (LP) technology
- Operating temperature from -20 °C to +85 °C

2. INTERFACES

2.1 Overview

This section summarizes the peripheral interfaces for the H22S75 chip as follows:

- (Section 2.2) SDRAM Interface
- (Section 2.3) Video Input (VIN) Interface
- (Section 2.4) Video Output (VOUT) Interfaces
- (Section 2.5) I2S Audio Interface
- (Section 2.6) Digital Microphone Interface (DMIC)
- (Section 2.7) Gigabit Ethernet MAC
- (Section 2.8) USB Interface
- (Section 2.9) Smart Media Input/Output (SMIO) Interface
- (Section 2.10) SSI / SPI Interface
- (Section 2.11) I2C / IDC Interface
- (Section 2.12) UART Interface
- (Section 2.13) General Purpose Input/Output (GPIO) Interface
- (Section 2.14) Analog-to-Digital Converter (ADC) Interface
- (Section 2.15) Real Time Clock (RTC) and Power Controller (PWC) Interfaces
- (Section 2.16) Stepper, Micro-Stepper, and Pulse Width Modulator (PWM) Interfaces
- (Section 2.17) JTAG Interface

2.2 SDRAM Interface

The H22S75 chip includes a synchronous DRAM interface, enabling high data-access rates in response to pipelined commands. The features of the H22S75 SDRAM interface include:

- Frequencies up to 1 GHz
- Support for the LPDDR3 / DDR3 / DDR3L low-power DDR interface
- Programmable I/O strength
- 32-bit data bus

Please contact an Ambarella representative to select a qualified Ambarella-approved DDR component.

2.3 Video Input (VIN) Interface

The H22S75 chip supports multiple serial and parallel input modes. The features of the H22S75 VIN interface include:

- Two sensor VIN instances - One VIN (Main) and one secondary:
- VIN (Primary, with all secondary units disabled):
 - 1-8 Lane SLVS (up to 3 Gbps per lane)
 - 1-4 Lane MIPI CSI-2 (up to 3 Gbps per lane)
 - 16-bit Parallel LVCMOS (up to 150 MHz) (YUV422)
- Secondary:
 - 1-4 Lane SLVS (up to 3 Gbps per lane)
 - 1-4 Lane MIPI CSI-2 (up to 3 Gbps per lane)
- Example use cases with 2 sensor inputs:
 - All 8 lanes are used by VIN
 - VIN and Secondary, each uses 4 lanes

Lane	VIN Only	VIN + Secondary
1	1 (VIN)	1 (VIN)
2	2 (VIN)	2 (VIN)
3	3 (VIN)	3 (VIN)
4	4 (VIN)	4 (VIN)
5	5 (VIN)	1 (Secondary)
6	6 (VIN)	2 (Secondary)
7	7 (VIN)	3 (Secondary)
8	8 (VIN)	4 (Secondary)

Table 2-1. Lane Sharing Between VIN and Secondary Inputs.

The H22S75 VIN module is part of the DSP cluster. Like other modules in the DSP cluster it is configured using a set of APIs. Please contact an Ambarella representative for information regarding VIN module configuration and other possible combinations for lane sharing.

2.4 Video Output (VOUT) Interfaces

The H22S75 Video Output (VOUT) interface supports a total of three output ports using two logical video channels.

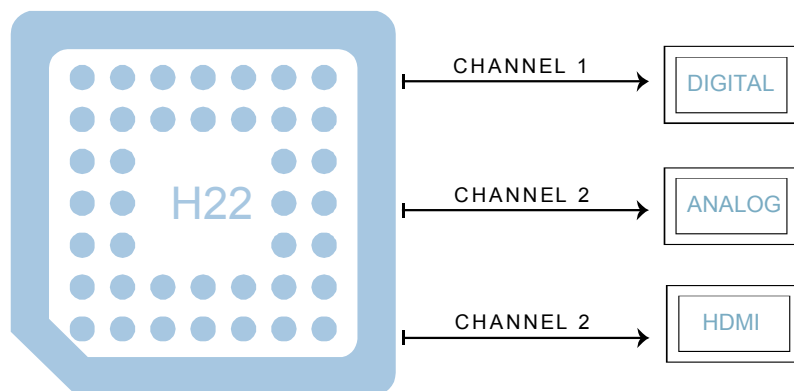


Figure 2-1. H22S75 Video Output Channels and Ports.

One VOUT channel is capable of driving digital output to RGB LCD panels, while the second VOUT channel drives either analog composite output or HDMI output to the on-chip HDMI transmitter (Tx) unit. The H22S75 chip supports simultaneous 1080i and 480i output rates.

2.4.1 Analog Video Output

The H22S75 video digital-to-analog converter (DAC) can drive standard-definition 480i/576i composite video outputs.

2.4.2 Digital Video Output

The H22S75 chip supports several digital video output modes including 8-bit or 16-bit {CbY, CrY}, LCD-RGB, and CCIR.601 as described in the tables below.

Bits	Mapped To Signal	Notes
VDO_OUT[15:8]	Unused	
VDO_OUT[7:0]	Interleaved R,G,B	VDO_OUT[7] is MSB

Table 2-2. Digital RGB Mode (Video Output Modes 0/1/2 for 3-bit Output to the LCD).

Bits	Mapped To Signal	Notes
VDO_OUT[15:11]	Upper 5 bits of the Red channel	VDO_OUT[15] is the MSB
VDO_OUT[10:5]	Upper 6 bits of the Green channel	VDO_OUT[10] is the MSB
VDO_OUT[4:0]	Upper 5 bits of the Blue channel	VDO_OUT[4] is the MSB

Table 2-3. 5:6:5 RGB Mode (Video Output Mode 3 for 16-bit RGB Output to the LCD).

Bits	Mapped To Signal	Notes
VDO_OUT[15:8]	Unused	

Bits	Mapped To Signal	Notes
VDO_OUT[7:0]	Interleaved Cb,Y,Cr,Y . . .	

Table 2-4. 8-bit YCbCr Mode (Video Output Mode 7).

Bits	Mapped To Signal	Notes
VDO_OUT[15:8]	Interleaved Cb,Cr	VDO_OUT[15] is the MSB
VDO_OUT[7:0]	Y	VDO_OUT[7] is the MSB

Table 2-5. 16-bit 601-YCbCr Mode (Video Output Mode 5).

Table 2-5 and Table 2-6 correspond to 4:2:2 output format.

2.4.3 HDMI Output

The H22S75 chip includes an embedded HDMI 2.0 transmitter that provides three lanes of transition-minimized differential signaling (TMDS) data and one clock lane. The features of the H22S75 HDMI interface include:

- Consumer Electronics Control (CEC) support, allowing command and control of up to 15 CEC-enabled devices
- An additional two-wire bus (IDC2) for secure key transfer (see [Section 2.11](#))

2.5 I2S Audio Interface

The H22S75 chip provides an Integrated Interchip Sound (I2S) controller for two-channel audio support. Features of the I2S interface include:

- Support for audio using an external audio codec analog-to-digital converter (ADC)
- I2S host interface support
- All data lanes are clocked by the same clock signal

2.6 Digital Microphone Interface (DMIC)

The H22S75 chip provides a digital microphone interface (DMIC).

2.7 Gigabit Ethernet MAC

- The H22S75 Ethernet controller supports 10/100/1000-Mbps data transfer rates with IEEE 802.3-compliant RGMII/RMII (default) interface and communicates with an external Gigabit/Fast Ethernet PHY
- The Ethernet controller supports MDIO Master interface (optional) for PHY device configuration and

management

2.7.1 Enable / Disable Ethernet

Ethernet functionality is enabled / disabled with power-on configuration bit POC[23], whether the Gigabit function (RGMII) is enabled or Ethernet RMII is used.

2.8 USB Interface

The H22S75 SoC includes one USB 2.0 port configurable as host or device, with a built-in PHY. Features of the H22S75 USB interface include:

- One configurable USB host/device, with a built-in PHY
- USB power-on boot mode
- The USB device can be used to burn firmware to flash or to simulate Ethernet for debugging.
- The USB host can be used to connect a USB WiFi module, a USB card reader, or 3G/4G baseband.

2.9 Smart Media Input/Output (SMIO) Interface

The H22S75 chip provides Smart Media Input/Output (SMIO) pins as a flexible storage-media interface for NAND Flash and SD controllers. Features of the H22S75 SMIO interface include:

- NAND Flash controller
 - Up to 8-Gbit device, 512-Byte and 2-KByte page sizes
 - 8-bit flash chip data bus
 - 4-bit and 8-bit single-level cell (SLC) memory with error-correcting code (ECC) hardware and read-confirm support
- Two SD controllers (SD0, SD1)
 - SD0:
 - SDIO v3.0, SD, SDHC, SDXC, MMC and eMMC operation with boot support and UHS-I speed
 - Support for 1-bit, 4-bit, and 8-bit SD mode
 - SD1:
 - SDIO v2.0, SD, SDHC, SDXC, MMC and eMMC operation
 - Support for 1-bit, 4-bit, and 8-bit SD mode
 - 32-GByte maximum capacity for SDHC SD Card
 - 2-TByte maximum capacity for SDXC SD Card
 - Cyclic redundancy check 7 (CRC-7) for command, and cyclic redundancy check 16 (CRC-16) for data integrity
- Power-on NAND Flash and eMMC boot modes
- SD0 may be used to connect to an SD card or an SDIO Wi-Fi module.

2.10 SSI / SPI Interface

The H22S75 chip provides three Synchronous Serial Interface (SSI) / Serial Peripheral Interface (SPI) masters and one dedicated SSI / SPI slave for full-duplex data transmission support. Features of the H22S75 SSI / SPI interface include:

- SSI / SPI master control with DMA support for up to eight slave devices
- Dedicated SSI / SPI slave port for connection to an external system master
- SPI-NOR, SPI-EEPROM boot support included with DMA support

Master	Number of Device Enables	Device Enable Pins	SSI/SPI Function	Default Polarity ¹
SSI0	4	SSIOEN0	ssi0_en0 Device Enable	Active Low
		SSIOEN1	ssi0_en1 Device Enable	Active Low
		SC_E0	ssi0_en2 Device Enable	Active Low
		TIMER2	ssi0_en3 Device Enable	Active Low
SSI1	4	ENET_RXD_0 or SC_A3	ssi1_en0 Device Enable	Active Low
		ENET_RXD_1 or SC_B0	ssi1_en1 Device Enable	Active Low
		ENET_RX_ER or SC_B1	ssi1_en2 Device Enable	Active Low
		ENET_CRS_DV or SC_B2	ssi1_en3 Device Enable	Active Low
SSI2	4	SSI2EN0	ssi2_en0 Device Enable	Active Low
		SSI2EN1	ssi2_en1 Device Enable	Active Low
		TIMER0	ssi2_en2 Device Enable	Active Low
		TIMER1	ssi2_en3 Device Enable	Active Low

Table 2-6. H22S75 SSI / SPI Master with Device Enable Detail.

Note:

1. Each SSI / SPI device-enable has programmable polarity; i.e., the polarity can be assigned to meet peripheral requirements without external glue logic.

2.11 I2C / IDC Interface

The H22S75 SoC includes three Inter-Integrated Circuit (I2C / IDC) interfaces to provide bidirectional data communication between the chip and its peripheral devices. Features of the H22S75 I2C / IDC interfaces include:

- Protocol speeds up to 400 Kbps
- Support for single-master mode

2.12 UART Interface

The H22S75 chip includes three Universal Asynchronous Receiver / Transmitter (UART) ports. Features of the H22S75 UART interface include:

- UART Port 0 doesn't have hardware flow control or direct memory access (DMA) support, and it is used for debugging
- UART Port 1 has hardware flow control and DMA support
- UART Port 2 (UART_AHB) is pin muxed with other functions and has hardware flow control and DMA support
- A maximum baud rate of 115.2 Kbps for UART0, based on per-port software settings
- UART_AHB can be used to connect to Bluetooth/GPS when other mux functions are not in use

2.13 General Purpose Input/Output (GPIO) Interface

The H22S75 SoC includes 138 CMOS pins which can be programmed for multi-use General Purpose Input/Output (GPIO) functions. Features of the H22S75 GPIO interface include:

- Pins with reduced electrostatic discharge sensitivity, tested to the latest JEDEC standard (*Joint Standard for Component-Level Electrostatic Discharge Sensitivity Testing*)
- Multiplexing support, allowing GPIO pins to be assigned multiple functions that can be independently enabled via software
- Individual pull-up/down control
- Individual drive strength control

2.14 Analog-to-Digital Converter (ADC) Interface

The H22S75 chip provides multiple channels for analog-to-digital conversion (ADC). Features of the H22S75 ADC interface include:

- Three channels
- High/low threshold interrupt generation
- 12-bit resolution

2.15 Real Time Clock (RTC) and Power Controller (PWC) Interfaces

To conserve power, the H22S75 system software optimizes clock and PLL frequencies according to operating mode. Peripheral clocks can be further optimized by the user through register programming.

Features of the power controller (PWC) and real-time clock (RTC) interfaces include:

- 32-bit embedded RTC maintained with one dedicated always-on power supply pin
- RTC provides current time, alarm set, and power-on and power-off sequence generation

2.16 Stepper, Micro-Stepper, and Pulse Width Modulator (PWM) Interfaces

2.16.1 Stepper and Micro-Stepper Motor Controllers

The H22S75 chip supports five stepper motor controller channels, each of which can be used for independent motor control. The chip also provides four sets of micro-stepper interfaces.

2.16.2 Pulse Width Modulator (PWM)

The H22S75 chip provides four pulse width modulation interfaces (PWMB0/B1/C0/C1):

- The four PWM outputs are referred to as pwm_[0:3]. Functionally:
 - PWMB0 is associated with pwm_0
 - PWMB1 is associated with pwm_1
 - PWMC0 is associated with pwm_2
 - PWMC1 is associated with pwm_3
- Note that in addition to the PWM controller embedded in the stepper motor controller, the H22S75 external pin **VD_PWM** can also serve as a PWM controller.
- Selection of PWM functions is executed via software. pwm_[0:3] are typically used for motor control and are sourced to the video input clock **CLK_SI**.

2.17 JTAG Interface

The H22S75 chip provides an interface for JTAG In-Circuit Emulator (ICE) debugging. Contact an Ambarella representative for more information regarding the JTAG interface.

3. PINS

3.1 Pins: Overview

The H22S75 SoC is equipped with 369 external physical pins including power balls, ground balls, and signal balls. This section provides pin details for the primary chip interfaces and functions.

- Refer to Section 4.4 for a list of fail-safe CMOS pins and their corresponding voltage thresholds.
- Refer to Chapter 7 for a complete list of pins sorted by their location on the H22S75 ball map.

3.2 Pins: Tables

This section lists the pins for each interface as follows:

- (Section 3.2.1) Pins: DRAM
- (Section 3.2.2) Pins: Sensor / Video Input
- (Section 3.2.3) Pins: Video Output
- (Section 3.2.4) Pins: I2S Digital Audio
- (Section 3.2.5) Pins: Ethernet Interface
- (Section 3.2.6) Pins: USB
- (Section 3.2.7) Pins: Smart Media Input/Output (SMIO)
- (Section 3.2.8) Pins: SSI / SPI
- (Section 3.2.9) Pins: I2C / IDC
- (Section 3.2.10) Pins: UART
- (Section 3.2.11) Pins: InfraRed Remote
- (Section 3.2.12) Pins: General Purpose Input/Output (GPIO)
- (Section 3.2.13) Pins: Analog to Digital Conversion (ADC)
- (Section 3.2.15) Pins: Real Time Clock (RTC)
- (Section 3.2.16) Pins: Timer
- (Section 3.2.17) Pins: Pulse Width Modulator (PWM)
- (Section 3.2.18) Pins: JTAG Control
- (Section 3.2.19) Pins: Global and Test
- (Section 3.2.20) Pins: Power, Ground and PLL

For each pin listed, the following information is provided:

- Pin direction: (I) input, (O) output, (S) supply, (G) ground
- Pad type
- A brief description
- For complete multiplexing information, please refer to [Section 3.2.12](#) and Chapter 7.

3.2.1 Pins: DRAM

Name	Location	Dir	Type	Description
DDR_CALIBR	A4	I/O	Analog	ZQ calibration
DDR_CK	K2	O	SSTL	DRAM clock per SDRAM
DDR_CK_BAR	K1	O	SSTL	DDR_CK and DDR_CK_BAR are differential clocks
DDR_CK_2_BAR	H1	O	SSTL	DDR_CK and DDR_CK_BAR are differential clocks
DDR_CK_2	H2	O	SSTL	DRAM clock per SDRAM
DDR_CKE_2	J1	O	SSTL	Clock enable for 2nd die
DDR_CKE	L1	O	SSTL	Clock enable
DDR_CS_2	C5	O	SSTL	Chip select for die 2
DDR_CS	B5	O	SSTL	Chip select for die 1
DDR_DM [3:0]	D2, B3, R2, R3	O	SSTL	Data write mask (1 bit per 8 data bits)
DDR_DQ [31:0]	B2, A1, C2, B1, F2, E1, E2, F1, A2, B4, A3, C4, F3, E4, E3, D4, P2, M1, N2, N1, T2, T1, U2, U1, M2, P4, M3, R4, T3, T4, U3, U4	I/O	SSTL	Bi-directional data bus
DDR_DQS [3:0]	C1, C3, R1, P3	I/O	SSTL	Data strobe (1 bit per 8 data bits) Output with write data, center-aligned Input with read data, edge-aligned
DDR_DQS_BAR [3:0]	D1, D3, P1, N3	I/O	SSTL	DDR_DQS [N] and DDR_DQS_BAR [N] are differential signals
DDR_VDDQ_CKE	E6	S	Digital Supply	Power for DDR_CKE and DDR_RESET pins
DDR_VDDQ	F5, G5, H5, J5, K5, L5, M5, N5	S	Digital Supply	DDR digital I/O power supply
DDR_ADDR [15:0]	L2, K3, G1, G2, H3, K4, R5, J4, P5, J3, D5, G3, F4, E5, L3, G4	O	SSTL	Address for row address strobe (RAS) and column address strobe (CAS)
DDR_WE	H4	O	SSTL	Write enable (active low)
DDR_BA [2:0]	U5, J2, T5	O	SSTL	Bank Address
DDR_ODT	L4	O	SSTL	SDRAM on-die termination control signal
DDR_RAS	M4	O	SSTL	Row address strobe (active low)
DDR_CAS	N4	O	SSTL	Column address strobe (active low)

Name	Location	Dir	Type	Description
DDR_VREF_[2:1]	A5, W5	I/O	SSTL	Reference Voltage for SSTL18 pad (0.5*DDR_VDDQ)
DDR_RESET	V5	O	SSTL	DDR3 - Asynchronous reset LPDDR2 - NC

Table 3-1. DRAM Pins.

3.2.2 Pins: Sensor / Video Input

Name	Location	Dir	Type	Description
CLK_SI	U6	I/O	CMOS	Sensor master clock output
CLK_SI2	V6	I/O	CMOS	Sensor master clock output
SD_LVDS_N_[0:7]	B10, B9, B8, B7, B15, B14, B13, B12	I	Sub-LVDS/ SLVS/ LVCMOS /MIPI	Sensor data Differential for sub-LVDS and MIPI Single-ended for LVCMOS mode.
SD_LVDS_P_[0:7]	A10, A9, A8, A7, A15, A14, A13, A12	I	Sub-LVDS/ SLVS/ LVCMOS /MIPI	Termination resistor built in for sub-LVDS / SLVS mode. Both single and double data rates supported.
SHSYNC	D8	O	CMOS	H-Sync / H-Valid with Master mode configuration
SPCLK_LVDS_N_[0:1]	B11, B6	I	Sub-LVDS/ SLVS/ LVCMOS /MIPI	Sensor pixel clock Differential pairs for sub-LVDS and SLVS mode.
SPCLK_LVDS_P_[0:1]	A11, A6	I	Sub-LVDS/ SLVS/ LVCMOS /MIPI	SPCLK_LVDS_P_0 is used for single-ended pixel clock with LVCMOS mode.
SVSYNC	D7	I/O	CMOS	V-Sync / V-Valid with Master mode configuration

Table 3-2. VIN Sensor Interface Pins.

3.2.3 Pins: Video Output

This section covers video output interface pins for Digital-to-Analog Conversion, Digital Video Output, and HDMI output.

3.2.3.1 VOUT Pins: Video Digital-to-Analog Conversion (DAC)

Name	Location	Dir	Type	Description
DAC_COMP	C9	I/O	Analog	Compensation pin
DAC_IO	D6	I/O	Analog	Composite CVBS output
DAC_RSET	C7	I/O	Analog	Reference resistor
DAC_VREFIN	C8	I/O	Analog	Voltage reference input

Table 3-3. Video DAC Pins.

3.2.3.2 VOUT Pins: Digital Video Output

Name	Location	Dir	Type	Description ¹
VD0_CLK	V4	I/O	CMOS	Video output clock
VD0_HSYNC	U8	I/O	CMOS	Video output HSync signal
VD0_HVLD	W7	I/O	CMOS	Video output valid signal
VD0_OUT_0	W6	I/O	CMOS	Video output data
VD0_OUT_1	W3	I/O	CMOS	Video output data
VD0_OUT_2	Y5	I/O	CMOS	Video output data
VD0_OUT_3	AA5	I/O	CMOS	Video output data
VD0_OUT_4	W1	I/O	CMOS	Video output data
VD0_OUT_5	Y3	I/O	CMOS	Video output data
VD0_OUT_6	W2	I/O	CMOS	Video output data
VD0_OUT_7	V7	I/O	CMOS	Video output data
VD0_OUT_8	U7	I/O	CMOS	Video output data
VD0_OUT_9	AA7	I/O	CMOS	Video output data
VD0_OUT_10	V3	I/O	CMOS	Video output data
VD0_OUT_11	W4	I/O	CMOS	Video output data
VD0_OUT_12	Y6	I/O	CMOS	Video output data
VD0_OUT_13	AA6	I/O	CMOS	Video output data
VD0_OUT_14	V1	I/O	CMOS	Video output data
VD0_OUT_15	V2	I/O	CMOS	Video output data
VD0_VSYNC	Y7	I/O	CMOS	Video output VSync signal

Table 3-4. Digital Video Output Pins.

Note:

1. H22S75 digital video output pins are used for power-on configuration (POC).

3.2.3.3 VOUT Pins: HDMI Output

Name	Location	Dir	Type	Description
HDMI_REXT	G21	I/O	Analog	Reference resistor - 10 KOhms (1% tolerance) (Required even if HDMI port is unused)
HDMI_AVDD33_ESD	A21	S	Analog Supply	HDMI analog power

Name	Location	Dir	Type	Description
HDMI_AVDD18_ESD	B21	S	Analog Supply	HDMI analog power
HDMI_CH2_M	C20	I/O	Analog	Transition-minimized differential signaling (TMDS) data out (open drain)
HDMI_CH2_P	C21			
HDMI_CH1_M	D20			
HDMI_CH1_P	D21			
HDMI_CH0_M	E20			
HDMI_CH0_P	E21			
HDMI_CLK_M	F20			
HDMI_CLK_P	F21			
CEC	F19	I/O	CMOS	Consumer Electronics Control (CEC) pin (3.3-V tolerance)
HPD	E19	I/O	CMOS	Hot-plug detect (3.3-V tolerance)

Table 3-5. HDMI Output Pins.

3.2.4 Pins: I2S Digital Audio

Name	Location	Dir	Type	Description
CLK_AU	AA12	O	CMOS	Master clock for external audio codec
I2S_CLK	U12	I/O	CMOS	I2S Controller audio bit clock
I2S_SI	V11	I	CMOS	I2S Controller serial data in
I2S_SO	W12	O	CMOS	I2S Controller serial data out
I2S_WS	Y12	I/O	CMOS	I2S Controller word select

Table 3-6. I2S Controller Pins.

3.2.5 Pins: Ethernet Interface

Name	Location	Dir	Type	Description
ENET_MDC	U9	I/O	CMOS	MII clock
ENET_CLK_RX	U10	I/O	CMOS	Reference clock
ENET_RXD_[3:0]	W11, W10, Y10, AA10	I/O	CMOS	Receive data
ENET_MDIO	V8	I/O	CMOS	MII data bus
ENET_CLK_TX	V9	I/O	CMOS	Transmit clock
ENET_GTX_CLK	Y9	I/O	CMOS	Ethernet clock
ENET_RXDV	Y11	I/O	CMOS	Receive data
ENET_TXD_[3:0]	AA9, AA8, Y8, W8	I/O	CMOS	Transmit data
ENET_TXEN	W9	I/O	CMOS	Transmit ready
ENET_EXT_OSC_CLK	AA11	I/O	CMOS	Ethernet external oscillator clock

Table 3-7. Ethernet Pins.

3.2.6 Pins: USB

Name	Location	Dir	Type	Description
GPIO_1	V16	I/O	CMOS	USB EHCI overcurrent detect input
GPIO_3	Y16	I/O	CMOS	USB EHCI port power enable out
DETECT_VBUS	D17	I/O	CMOS	USB slave bus detect
USB_DM	B16	I/O	Analog	USB data. DP/DM are differential signals.
USB_DP	A16	I/O	Analog	
USB_REXT	C17	I/O	Analog	USB resistor

Table 3-8. USB Interface Pins.

3.2.7 Pins: Smart Media Input/Output (SMIO)

- The Smart Media Input/Output (SMIO) pins are CMOS type and programmable input/output.
- SMIO pins are shared by controllers for NAND Flash (NAND) and SD / SDIO / SDHC / SDXC / MMC / eMMC (SD).
- SMIO pins use **SMIO_[N]** for the primary function name.

Name	Location	NAND		SD		Description
		Function	Dir	Function	Dir	
SMIO_0	R19	nand_ce	O			NAND chip enable
SMIO_1	R18	nand_rb	I/O			NAND ready / busy
SMIO_2	L19			sd_clk	O	SD0 clock
SMIO_3	M18			sd_cmd	I/O	SD0 command
SMIO_4	M20			sd_cd	I	SD0 card detect
SMIO_5	M19			sd_wp	I	SD0 write protect
SMIO_6	R20	nand_re	O			NAND read enable
SMIO_7	P21	nand_we	O			NAND write enable
SMIO_8	R21	nand_ale	O			NAND address latch enable
SMIO_9	P20	nand_d[0]	I/O			NAND data
SMIO_10	P19	nand_d[1]	I/O			NAND data
SMIO_11	P18	nand_d[2]	I/O			NAND data
SMIO_12	P17	nand_d[3]	I/O			NAND data
SMIO_13	N17	nand_d[4]	I/O			NAND data
SMIO_14	N18	nand_d[5]	I/O			NAND data
SMIO_15	N19	nand_d[6]	I/O			NAND data
SMIO_16	N20	nand_d[7]	I/O			NAND data
SMIO_17	N21	nand_cle	O			NAND command latch enable
SMIO_18	L20			sd_d[0]	I/O	SD0 data
SMIO_19	K21			sd_d[1]	I/O	SD0 data
SMIO_20	J17			sd_d[2]	I/O	SD0 data
SMIO_21	K17			sd_d[3]	I/O	SD0 data
SMIO_22	L21			sd_d[4]	I/O	SD0 data

Name	Location	NAND		SD		Description
		Function	Dir	Function	Dir	
SMIO_23	K20			sd_d[5]	I/O	SD0 data
SMIO_24	L18			sd_d[6]	I/O	SD0 data
SMIO_25	L17			sd_d[7]	I/O	SD0 data
SMIO_26	K19			sdxc_clk	O	SD1 clock
SMIO_27	K18			sdxc_cmd	I/O	SD1 command
SMIO_28	J18			sdxc_d[0]	I/O	SD1 data
SMIO_29	J19			sdxc_d[1]	I/O	SD1 data
SMIO_30	J20			sdxc_d[2]	I/O	SD1 data
SMIO_31	J21			sdxc_d[3]	I/O	SD1 data
SMIO_32	H21			sdxc_cd	I	SD1 card detect
SMIO_33	H20			sdxc_wp	I	SD1 write protect
SMIO_34	H19			sdxc_d[4]	I/O	SD1 data
SMIO_35	H18			sdxc_d[5]	I/O	SD1 data
SMIO_36	G18			sdxc_d[6]	I/O	SD1 data
SMIO_37	G19			sdxc_d[7]	I/O	SD1 data
SMIO_38	M17			sd_reser	O	SD0 reset
SMIO_39	G20			sdxc_reset	O	SD1 reset
WP	M21	nand_wp	O			NAND write protect

Table 3-9. Storage Media Interface Pins (SMIO) in NAND Flash and SD Modes.

3.2.8 Pins: SSI / SPI

Name	Location	Dir	Pad Type	Description
SSI0CLK	AA19	I/O	CMOS	ssi0 master port bit clock
SSI0EN0	R17	O	CMOS	ssi0_en0 device enable
SSI0EN1	T17	O	CMOS	ssi0_en1 device enable
TIMER2	AA20	I/O	CMOS	ssi0_en3 device enable
ENET_RXD_0	AA10	I/O	CMOS	ssi1_en0 device enable
ENET_RXD_1	Y10	I/O	CMOS	ssi1_en1 device enable
SSI0MISO	Y18	I	CMOS	ssi0 master port data in
SSI0MOSI	AA18	O	CMOS	ssi0 master port data out

Table 3-10. SSI / SPI Interface Pins.

3.2.9 Pins: I2C / IDC

Name	Location	Dir	Pad Type	Description
IDCCLK	AA15	I/O	CMOS	First IDC serial port - clock
IDCDATA	U14	I/O	CMOS	First IDC serial port - data
IDC2CLK	V13	I/O	CMOS	Second IDC serial port - clock

Name	Location	Dir	Pad Type	Description
IDC2DATA	W14	I/O	CMOS	Second IDC serial port - data
IDC3CLK	Y14	I/O	CMOS	Third IDC serial port - clock
IDC3DATA	AA14	I/O	CMOS	Third IDC serial port - data

Table 3-11. I2C / IDC Interface Pins.

3.2.10 Pins: UART

Name	Location	Dir	Pad Type	Description
UART0RX	AA17	I	CMOS	UART Port 0 receive
UART0TX	AA16	O	CMOS	UART Port 0 transmit
UART1RX	W17	I	CMOS	UART Port 1 receive
UART1TX	Y17	O	SMOS	UART Port 1 transmit
UART1CTSN	U16	I	CMOS	UART clear to send from modem
UART1RTSN	U17	O	CMOS	UART request to send from Terminal/computer

Table 3-12. UART Interface Pins.

3.2.11 Pins: InfraRed Remote

Name	Location	Dir	Pad Type	Description
IR_IN	C19	I	CMOS	InfraRed input

Table 3-13. InfraRed Remote Interface Pins.

3.2.12 Pins: General Purpose Input/Output (GPIO)

The table below lists the General-Purpose Input/Output (GPIO) pins on the H22S75 chip. GPIO pins have multi-function capabilities and are CMOS-type programmable input/output. The function name that appears on the chip ball map is indicated in the **Pin Name** column. Refer to Chapter 7 for map locations.

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
0	GPIO_0	sd_hs_sel				
1	GPIO_1	ehci_app_prt_ovcurr0	uart2_ahb_rx	ssis_sclk	sc_c0	
2	GPIO_2	ehci_app_prt_ovcurr1	uart2_ahb_tx	ssis_rxd	sc_c1	
3	GPIO_3	ehci_prt_pwr_0	uart2_ahb_cts_n	ssis_txd	sc_c2	
4	GPIO_4	ehci_prt_pwr_1	uart2_ahb_rts_n	ssis_en	sc_c3	
5	GPIO_5	pwm_1	idsp_pip_iopad_master_hsync	vin_strig0	sc_d0	uart2_ahb_cts_n

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
6	GPIO_6	pwm_2	idsp_pip_iopad_ master_vsync	vin_strig1	sc_d1	uart2_ahb_rts_n
7	GPIO_7	sdxs_hs_sel				
8	SC_A0	sc_a0	ssi1_sclk	norspi_clk	pwm_0	
9	SC_A1	sc_a1	ssi1_txd	norspi_dq[0]	pwm_1	
10	SC_A2	sc_a2	ssi1_rxd	norspi_dq[1]	pwm_2	
11	SC_A3	sc_a3	ssi1_en0	norspi_dq[2]	pwm_3	
12	SC_B0	sc_b0	ssi1_en1	norspi_dq[3]		
13	SC_B1	sc_b1	ssi1_en2	norspi_en0	norspi_dq[2]	
14	SC_B2	sc_b2	ssi1_en3	norspi_en[1]	norspi_dq[3]	
15	SC_B3	sc_b3	pwm_3	norspi_en[2]		
16	SC_C0	sc_c0	uart2_ahb_rx	ssis_sclk		
17	SC_C1	sc_c1	uart2_ahb_tx	ssis_rxd		
18	SC_C2	sc_c2	uart2_ahb_cts_n	ssis_txd		
19	SC_C3	sc_c3	uart2_ahb_rts_n	ssis_en		
20	SC_D0	sc_d0	uart2_ahb_rx	ssis_sclk		pwm_0
21	SC_D1	sc_d1	uart2_ahb_tx	ssis_rxd		pwm_1
22	SC_D2	sc_d2	uart2_ahb_cts_n	ssis_txd		pwm_2
23	SC_D3	sc_d3	uart2_ahb_rts_n	ssis_en		pwm_3
24	SC_E0	sc_e0	ssi0_en2	norspi_en[3]		pwm_1
25	TIMER0	tm11_clk	ssi2_en2			
26	TIMER1	tm12_clk	ssi2_en3	idsp_pip_iopad_ master_hsync		
27	TIMER2	tm13_clk	ssi0_en3	idsp_pip_iopad_ master_vsync		
28	IDCCLK	idc0clk				
29	IDCDATA	idc0data				
30	IDC2CLK	idc1clk		norspi_dq[2]	norspi_en[2]	
31	IDC2DATA	idc1data		norspi_dq[3]	norspi_en[3]	
32	IDC3CLK	idc2clk	vin_strig0			
33	IDC3DATA	idc2data	vin_strig1			
34	IR_IN	ir_in				
35	SSI0CLK	ssi0_sclk	norspi_clk	uart2_ahb_rx	ssis_sclk	
36	SSI0MOSI	ssi0_txd	norspi_dq[0]	uart2_ahb_tx	ssis_rxd	
37	SSI0MISO	ssi0_rxd	norspi_dq[1]	uart2_ahb_cts_n	ssis_txd	
38	SSI0ENO	ssi0_en0	norspi_en[0]	uart2_ahb_rts_n	ssis_en	
39	SSI0EN1	ssi0_en1	norspi_en[1]			
40	SSI2CLK	ssi2_sclk	idc3clk			
41	SSI2MOSI	ssi2_txd	idc3data			
42	SSI2MISO	ssi2_rxd				
43	SSI2ENO	ssi2_en0				
44	SSI2EN1	ssi2_en1				
45	UART0RX	uart0rx	uart2_ahb_rx			
46	UART0TX	uart0tx	uart2_ahb_tx			
47	UART1RX	uart1_ahb_rx				
48	UART1TX	uart1_ahb_tx				

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
49	UART1CTSN	uart1_ahb_cts_n				
50	UART1RTSN	uart1_ahb_rts_n				
51	I2S_CLK	i2s_clk	dmic_clk			
52	I2S_SI	i2s_si	dmic_dat			
53	I2S_SO	i2s_so				
54	I2S_WS	i2s_ws				
55	CLK_AU	clk_au				
56	ENET_TXEN	enet_txen	sc_a0	enet_txen	ssi1_txd	norspi_en[0]
57	ENET_TXD_0	enet_txd_0	sc_a1	enet_txd_0	ssi1_en0	norspi_en[1]
58	ENET_TXD_1	enet_txd_1	sc_a2	enet_txd_1	ssi1_en1	norspi_en[2]
59	ENET_TXD_2		sc_a3	enet_txd_2	ssi1_en2	
60	ENET_TXD_3		sc_b0	enet_txd_3	ssi1_en3	
61	ENET_RXD_0	enet_rxd_0	sc_b1	enet_rxd_0	ssi1_rxd	norspi_dq[0]
62	ENET_RXD_1	enet_rxd_1	sc_b2	enet_rxd_1		norspi_dq[1]
63	ENET_RXD_2		sc_b3	enet_rxd_2		norspi_dq[2]
64	ENET_RXD_3			enet_rxd_3		norspi_dq[3]
65	ENET_RXDV	enet_rxdv		enet_rxdv		
66	ENET_MDC	enet_mdc		enet_mdc		
67	ENET_MDIO	enet_mdio		enet_mdio		
68	ENET_CLK_TX	enet_2nd_ref_clk		enet_clk_tx		
69	ENET_CLK_RX	enet_ref_clk		enet_clk_rx		
70	ENET_GTX_CLK	enet_gtx_clk		enet_gtx_clk		
71	ENET_EXT_OSC_CLK			enet_ext_osc_clk		
72	WP		nand_wp			
73	SMIO_0		nand_ce	norspi_clk		
74	SMIO_1		nand_rb	norspi_dq[4]		
75	SMIO_2		sd_clk			
76	SMIO_3		sd_cmd			
77	SMIO_4		sd_cd			
78	SMIO_5		sd_wp			
79	SMIO_6		nand_re	norspi_dq[5]		
80	SMIO_7		nand_we	norspi_dq[6]		
81	SMIO_8		nand_ale	norspi_dq[7]		
82	SMIO_9		nand_d[0]	norspi_en[0]		
83	SMIO_10		nand_d[1]	norspi_en[1]		
84	SMIO_11		nand_d[2]	norspi_en[2]		
85	SMIO_12		nand_d[3]	norspi_en[3]		

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
86	SMIO_13		nand_d[4]	norspi_dq[0]		
87	SMIO_14		nand_d[5]	norspi_dq[1]		
88	SMIO_15		nand_d[6]	norspi_dq[2]		
89	SMIO_16		nand_d[7]	norspi_dq[3]		
90	SMIO_17		nand_cle			
91	SMIO_18		sd_d[0]			
92	SMIO_19		sd_d[1]			
93	SMIO_20		sd_d[2]			
94	SMIO_21		sd_d[3]			
95	SMIO_22		sd_d[4]		sc_c0	ssis_sclk
96	SMIO_23		sd_d[5]		sc_c1	ssis_rxd
97	SMIO_24		sd_d[6]		sc_c2	ssis_txd
98	SMIO_25		sd_d[7]		sc_c3	ssis_en
99	SMIO_26		sdxc_clk			
100	SMIO_27		sdxc_cmd			
101	SMIO_28		sdxc_d[0]		sc_d0	ssis_sclk
102	SMIO_29		sdxc_d[1]		sc_d1	ssis_rxd
103	SMIO_30		sdxc_d[2]		sc_d2	ssis_txd
104	SMIO_31		sdxc_d[3]		sc_d3	ssis_en
105	SMIO_32		sdxc_cd			
106	SMIO_33		sdxc_wp			
107	SMIO_34		sdxc_d[4]			
108	SMIO_35		sdxc_d[5]			
109	SMIO_36		sdxc_d[6]			
110	SMIO_37		sdxc_d[7]			
111	SMIO_38		sd_reset			
112	SMIO_39		sdxc_reset			
113	HPD	hdmitx_hpd				
114	CEC	hdmitx_cec				
115	SVSYNC	vin_svsync	idsp_pip_iopad_ master_hsync			
116	SHSYNC	vin_shsync	idsp_pip_iopad_ master_vsync			
117	SENSOR_ RST					
118	VDO_OUT_0	vd0_out[0]				
119	VDO_OUT_1	vd0_out[1]				
120	VDO_OUT_2	vd0_out[2]				
121	VDO_OUT_3	vd0_out[3]				
122	VDO_OUT_4	vd0_out[4]				
123	VDO_OUT_5	vd0_out[5]				
124	VDO_OUT_6	vd0_out[6]				
125	VDO_OUT_7	vd0_out[7]				
126	VDO_OUT_8	vd0_out[8]				
127	VDO_OUT_9	vd0_out[9]				
128	VDO_ OUT_10	vd0_out[10]				

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
129	VDO_OUT_11	vd0_out[11]				
130	VDO_OUT_12	vd0_out[12]				
131	VDO_OUT_13	vd0_out[13]				
132	VDO_OUT_14	vd0_out[14]				
133	VDO_OUT_15	vd0_out[15]				
134	VDO_CLK	vd0_clk				
135	VDO_VSYNC	vd0_vsync				
136	VDO_HSYNC	vd0_hsync				
137	VDO_HVLD	vd0_hvld				
138	VD_PWM	pwm_0				

Table 3-14. General Purpose Input Output (GPIO) Multifunction-Capable Pins.

3.2.13 Pins: Analog to Digital Conversion (ADC)

Name	Location	Dir	Type	Description
ADC_CH[1:3]	E7, E8, E9	I	Analog	ADC analog input (3 channels)

Table 3-15. ADC Interface Pins.

3.2.14 Pins: Power Controller (PWC) and Real Time Clock (RTC)

Name	Location	Dir	Type	Description
XI_RTC	B18	I	XOSC	Connect to RTC crystal
XO_RTC	A18	O	XOSC	Connect to RTC crystal
PWC_WKUP	A19	I	CMOS	In the power-off state, a positive pulse can only trigger a power-on sequence
PWC_PSEQ[3:1]	B19, C18, A20	O	CMOS	Power up/ down control signals
PWC_RSTINB	B20	I	CMOS	PWC reset input. Usually pulled up to PWC_PC_VDD through an RC circuit.
PWC_AVDD33	D18	O	CMOS	PWC power
PWC_RSTOB	D19	O	CMOS	Reset signal out (also used as Power up/down signal)
PWC_AVDD18	E18	O	CMOS	UTE power

Table 3-16. PWC and RTC Interface Pins.

3.2.15 Pins: Real Time Clock (RTC)

Name	Location	Dir	Type	Description
PWC_AVDD18	E18	S	Analog Supply	Power for RTC module and on-chip RTC oscillator. When RTC_CP is less than a specified voltage, the power controller will shut down and all registers will reset.
XI_RTC	B18	I	XOSC	Connect to RTC crystal
XO_RTC	A18	O		

Table 3-17. RTC Interface Pins.

3.2.16 Pins: Timer

Name	Location	Dir	Type	Description
TIMER0	AA21	I/O	CMOS	Interval Timer 0 external clock source
TIMER1	W18	I/O	CMOS	Interval Timer 1 external clock source
TIMER2	AA20	I/O	CMOS	Interval Timer 2 external clock source

Table 3-18. Timer Pins.

3.2.17 Pins: Pulse Width Modulator (PWM)

Name	Location	Dir	Type	Description
VD_PWM	Y4	I/O	CMOS	Pulse Width Modulator Output

Table 3-19. PWM Pins.

3.2.18 Pins: JTAG Control

Name	Location	Dir	Pad Type	Description
JTAG_CLK	W13	I	CMOS	Clock
JTAG_RST_L	AA13	I	CMOS	Reset
JTAG_TDI	U13	I	CMOS	Data in
JTAG_TDO	Y13	O	CMOS	Data out
JTAG_TMS	V12	I	CMOS	Test mode select

Table 3-20. JTAG Pins.

3.2.19 Pins: Global and Test

Name	Location	Dir	Type	Description
POR_L	U11	I	CMOS	Power-on reset pin (active low)
TEST_MODE	V10	I	CMOS	0 - Normal mode 1 - Test mode
XIN	A17	I	XOSC	24-MHz or 48-MHz crystal or crystal oscillator input
XOUT	B17	O		
FSOURCE_0	Y19	S	Power / ground	Power supply for Efuse programming. Customer ties to digital ground for normal operation.
VDDWL_0	Y20	P	Power/ Ground	Power supply for Efuse programming. Customer ties to digital ground for normal operation.

Table 3-21. Global and Test Pins.

3.2.20 Pins: Power, Ground and PLL

Name	Location	Dir	Type	Description
AVDD33	E16	S	Analog Supply	3.3V Analog power supply
AVSS	C13, C14	G	Analog Ground	ADC analog ground
VDDI	H9, H11, H13, J9, J11, J13, K9, K11, K13, L9, L11, L13, M9, M11, M13, N9, N11, N13, P9,	S	Digital Supply	Digital power supply, 0.8V nominal
SD_VDDO	K14, L14	S	Digital Supply	SD controller digital IO power
VDDO	G17, P11, P12, P13	S	IO Power	IO Power
VDDP	F17, P8	S	IO Power	IO predriver Power, 1.8V nominal
VSSI	C6, C10, C11, C12, C15, C16, D9, D10, D11, E10, E11, E12, E13, E14, E15, F18, H8, H10, H12, H14, J8, J10, J12 J14, K8, K10, K12, L8, L10, L12, M8, M10, M12, M14, N8, N10, N12, N14, P10, P14	G	Digital Ground	Digital ground
AVDD	D13	S	Analog Supply	Analog power supply, 0.8V nominal
AVDD18	D12, D15	S	Analog Supply	Analog power supply, 1.8V nominal
MIPI_ANA_AVDD18_IO	D14	P	Digital Power	MIPI CMOS IO Power for MIPI LS or LVCMOS RX
DVDD	D16	P	Digital Power	Digital Power Analog block, 0.8V nominal
SDXC_VDDO	E17	O	Digital Power	Digital IO Power for SDXC, 3.3V / 1.8V

Name	Location	Dir	Type	Description
NAND_VDDO	H17	P	Digital Power	Digital IO Power for NAND, 3.3V / 1.8V

Table 3-22. Power, Ground and PLL Pins.

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4. ELECTRICAL CHARACTERISTICS

4.1 Electrical: Overview

This chapter provides details on the electrical characteristics of the H22S75 chip as follows:

- (Section 4.1) Electrical: Overview
- (Section 4.2) Electrical: Absolute Ratings
- (Section 4.3) Electrical: Recommended Operating Conditions
- (Section 4.4) Electrical: Fail-Safe Pins
- (Section 4.5) Electrical: Video Signal Wave Forms and Timing
- (Section 4.6) Electrical: SD Controller Timing
- (Section 4.7) Electrical: eMMC Boot Timing

Note that the electrical details provided in this chapter are preliminary estimates.

4.2 Electrical: Absolute Ratings

The following table provides absolute ratings for the nominal analog/digital voltages of the H22S75 power rails.

Parameter	Minimum	Maximum
Analog supply voltage (3.0 V)	-0.3 V	3.6 V
Digital supply voltage (3.0 V)	-0.3 V	3.6 V
Analog supply voltage (1.8 V)	-0.3 V	1.98 V
Digital supply voltage (1.8 V)	-0.3 V	1.98 V
Analog supply voltage (0.9 V)	-0.3 V	0.95 V
Digital supply voltage (0.8 V)	-0.3 V	0.95 V
Digital I/O range (V)	-0.3 V	3.6 V
	-0.3 V	1.98 V
Analog I/O range (V)	-0.3 V	3.6 V
	-0.3 V	1.98 V
Operating temperature (case) (°C)	-20 °C	85 °C

Table 4-1. Absolute Ratings.

This Ambarella part will support a full range of operation at the case temperature specified above, provided that the customer's PCB design, manufacturing processes, and power supply design are equal to those of the Ambarella reference hardware platform in terms of quality. All other components used during system design are also required to operate successfully at the case temperature range specified above to guarantee proper overall system operation.

4.3 Electrical: Recommended Operating Conditions

This section continues with recommended operating conditions for:

- (Section 4.3.1) Operating Conditions: Power Rails - DC Characteristics
- (Section 4.3.2) Operating Conditions: Digital I/O
- (Section 4.3.3) Operating Conditions: DRAM I/O
- (Section 4.3.4) Operating Conditions: PWC and RTC Power Supply
- (Section 4.3.5) Operating Conditions: Video Input
- (Section 4.3.6) Operating Conditions: Video DAC
- (Section 4.3.7) Operating Conditions: ADC Electrical Specifications
- (Section 4.3.8) Operating Conditions: Crystal and Reference Clock Requirements

4.3.1 Operating Conditions: Power Rails - DC Characteristics

Parameter ¹	Comments	Minimum	Typical	Maximum	Ripple
DDR[0:1]_VDDQ_CKE / DDR[0:1]_VDDQ	LPDDR2/3 Mode	1.14 V	1.2 V	1.3 V	2%
	DDR3 Mode	1.4 V	1.5 V	1.6 V	2%
	DDR3L Mode	1.28 V	1.35 V	1.45 V	2%
	-	-	-	-	-
AVDD		0.8 V	0.85 V	0.9 V	2%
DVDD		0.8 V	0.85 V	0.9 V	2%
AVDD18		1.7 V	1.8 V	1.9 V	2%
HDMI_AVDD18_ESD		1.7 V	1.8 V	1.9 V	2%
PWC_AVDD33		3.0 V	3.3 V	3.6 V	2%
PWC_AVDD18		0.7 V	1.8 V	1.98 V	2%
AVDD33		2.85 V	3.0 V	3.6 V	2%
VDDI		0.83 V	0.85 V	0.87 V	2%
VDDO	3.0-V mode	2.85 V	3.0 V	3.6 V	2%
	1.8-V mode	1.7 V	1.8 V	1.9 V	2%
VDDO_NAND	3.0-V mode	2.85 V	3.0 V	3.6 V	2%
	1.8-V mode	1.7 V	1.8 V	1.9 V	2%
VDDO_SD / VDDO_ SDXC	SD / SDIO mode	2.85 V	3.0 V	3.6 V	2%
	SDXC mode	1.7 V	1.8 V	1.9 V	2%
VDDP		1.7 V	1.8 V	1.9 V	2%
-		-	-	-	-
-		-	-	-	-

Table 4-2. Power Rails: DC Characteristics (Preliminary and Subject to Change).

Note:

1. The electrical details provided in this chapter are preliminary estimates and are subject to change. Please contact an Ambarella representative for current electrical specifications.

2. Please ensure that the voltage setting is not lower than 0.69 V.
- 3.

4.3.2 Operating Conditions: Digital I/O

Parameter	Comments	Minimum	Typical	Maximum
VIL	Input Low Voltage	-0.3 V		0.7 V
VIH	Input High Voltage	2.0 V		3.6 V (for 3.3 V-tolerant pins)
VOL	Output Low Voltage			0.4 V
VOH	Output High Voltage	2.4 V		

Table 4-3. Digital I/O Characteristics (Preliminary).

4.3.3 Operating Conditions: DRAM I/O

4.3.3.1 DRAM: DC Supply Voltage Levels

Parameter	Comments	Minimum	Typical	Maximum
DDR[0:1]_VDDQ		See Section 4.3.1		
DDR[0:1]_VDDQ_CKE		See Section 4.3.1		
-		-		
-		-		
VTT	Termination voltage	DDR_VREF - 0.04 V	DDR_VREF	DDR_VREF + 0.04 V
DDR[0:1]_VREF	Input reference level	0.49 * DDR_VDDQ	0.5 * VDDQ	0.51 * DDR_VDDQ

Table 4-4. DRAM I/O Characteristics - DC Supply Voltage Levels (Preliminary).

4.3.3.2 DRAM: SSTL I/O DC Specifications

Parameter	Comments	Minimum	Typical	Maximum
VIHT	DC input logic threshold high			DDR_VREF + 0.05 V
VILT	DC input logic threshold low	DDR_VREF - 0.05 V		
VIH	DC input voltage high	DDR_VREF + 100 mV		VDDQ + 0.3 V

Parameter	Comments	Minimum	Typical	Maximum
VIL	DC input voltage low	-0.3 V		DDR_VREF - 100 mV
VOH	DC output logic high	DDR_VDDQ		
VOL	DC output logic low			0 V
RTT1	RTT effective impedance	60 Ohms	75 Ohms	90 Ohms
RTT2	RTT effective impedance	120 Ohms	150 Ohms	180 Ohms

Table 4-5. DRAM I/O Characteristics - SSTL I/O DC Specifications (Preliminary).

4.3.4 Operating Conditions: PWC and RTC Power Supply

Parameter	Comments	Minimum	Typical	Maximum
PWC_AVDD18	RTC module supply	0.7 V	1.8 V	1.98 V
PWC_AVDD33	Power management supply	3.0 V	3.3 V	
VIH	For PWC_WKUP	1.7 V		
VIL	For PWC_WKUP			1.0 V
VOH	PWC_PSEQ[1:3], PWC_RSTOB	1.5 V		
VOL	VOH(min)=1.5V at 10uA loading; Need to add buffer for higher loadings.			0.5 V

Table 4-6. PWC and RTC Supply.

4.3.5 Operating Conditions: Video Input

4.3.5.1 VIN: SLVS / LVCMOS I/O

Parameter	Symbol	Comment	Min	Typ.	Max.
Digital Input Voltage	VIL	LVCMOS 1.2 V			0.5 V
		LVCMOS 1.8 V			0.6 V
	VIH	LVCMOS 1.2 V	0.8 V		
		LVCMOS 1.8 V	1.2 V		
Differential Input for SLVS	V _{CM}		0.2 V		1.0 V
	V _{DIFF}		70 mV		400 mV

Table 4-7. DC Characteristics: SLVS Interface.

4.3.6 Operating Conditions: Video DAC

Parameter	Comments	Minimum	Typical	Maximum
I_{OFS}	IO out current		34.6 mA	
I_{OP}	Operating Current		36 mA	
$V(IO)$	Out voltage full scale	1.17 V	1.28 V	1.43 V
Resolution	DAC resolution			10 bits
DNL	Differential non-linearity error			± 1 LSB
INL	Integral non-linearity error			± 2 LSB
VREF	Reference Voltage			1.22 V

Table 4-8. Video DAC Electrical Specifications.

4.3.7 Operating Conditions: ADC Electrical Specifications

4.3.7.1 ADC Electrical: DC Specification

Parameter	Comments	Minimum	Typical	Maximum
VREF	Reference Voltage (Top) (Low reference is ADC_AVSS)	ADC_AVDD	ADC_AVDD	ADC_AVDD
VIN	Analog input voltage	ADC_AVSS		VREF
N	Resolution		12 bits	
INL	INL		± 1 LSB	± 4 LSB
DNL	DNL		± 0.5 LSB	± 1 LSB

Table 4-9. ADC DC Specification.

4.3.7.2 ADC Electrical: AC Specification

Parameter	Comments	Minimum	Typical	Maximum
F_s	Sampling rate	50 K		1 MS/s
FCLK	Sampling clock		12 MHz	

Parameter	Comments	Minimum	Typical	Maximum
SNDR	Signal-to-noise and distortion ratio (Fclk = 5 MHz and AIN = 50 KHz*)	54 dB	60 dB	

Table 4-10. ADC AC Specification.

4.3.8 Operating Conditions: Crystal and Reference Clock Requirements

4.3.8.1 Crystal and Reference Clock Requirements: 24 MHz

Description	Minimum	Typical	Maximum
Crystal frequency	N/A	24 MHz only	N/A
Crystal accuracy			± 30 PPM
Cycle-to-cycle jitter			± 200 ps
Long-term jitter			± 500 ps

Table 4-11. Jitter Specifications.

4.3.8.2 Crystal and Reference Clock Requirements: 32.768 KHz

Description	Minimum	Typical	Maximum
Crystal accuracy			± 30 PPM

Table 4-12. Jitter Specifications (32.768 KHz).

4.4 Electrical: Fail-Safe Pins

The H22S75 chip provides a number of fail-safe CMOS pins that can have active signals at or below 3.6 V when the H22S75 is powered down.

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
0	GPIO_0	sd_hs_sel				
1	GPIO_1	ehci_app_prt_ovcurr0	uart2_ahb_rx	ssis_sclk	sc_c0	
2	GPIO_2	ehci_app_prt_ovcurr1	uart2_ahb_tx	ssis_rxd	sc_c1	
3	GPIO_3	ehci_prt_pwr_0	uart2_ahb_cts_n	ssis_txd	sc_c2	
4	GPIO_4	ehci_prt_pwr_1	uart2_ahb_rts_n	ssis_en	sc_c3	
5	GPIO_5	pwm_1	idsp_pip_iopad_master_hsync	vin_strig0	sc_d0	uart2_ahb_cts_n
6	GPIO_6	pwm_2	idsp_pip_iopad_master_vsync	vin_strig1	sc_d1	uart2_ahb_rts_n

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
7	GPIO_7	sdxs_hs_sel				
8	SC_A0	sc_a0	ssi1_sclk	norspi_clk	pwm_0	
9	SC_A1	sc_a1	ssi1_txd	norspi_dq[0]	pwm_1	
10	SC_A2	sc_a2	ssi1_rxd	norspi_dq[1]	pwm_2	
11	SC_A3	sc_a3	ssi1_en0	norspi_dq[2]	pwm_3	
12	SC_B0	sc_b0	ssi1_en1	norspi_dq[3]		
13	SC_B1	sc_b1	ssi1_en2	norspi_en0	norspi_dq[2]	
14	SC_B2	sc_b2	ssi1_en3	norspi_en[1]	norspi_dq[3]	
15	SC_B3	sc_b3	pwm_3	norspi_en[2]		
16	SC_C0	sc_c0	uart2_ahb_rx	ssis_sclk		
17	SC_C1	sc_c1	uart2_ahb_tx	ssis_rxd		
18	SC_C2	sc_c2	uart2_ahb_cts_n	ssis_txd		
19	SC_C3	sc_c3	uart2_ahb_rts_n	ssis_en		
20	SC_D0	sc_d0	uart2_ahb_rx	ssis_sclk		pwm_0
21	SC_D1	sc_d1	uart2_ahb_tx	ssis_rxd		pwm_1
22	SC_D2	sc_d2	uart2_ahb_cts_n	ssis_txd		pwm_2
23	SC_D3	sc_d3	uart2_ahb_rts_n	ssis_en		pwm_3
24	SC_E0	sc_e0	ssi0_en2	norspi_en[3]		pwm_1
25	TIMER0	tm11_clk	ssi2_en2			
26	TIMER1	tm12_clk	ssi2_en3	idsp_pip_iopad_master_hsync		
27	TIMER2	tm13_clk	ssi0_en3	idsp_pip_iopad_master_vsync		
28	IDCCLK	idc0clk				
29	IDCDATA	idc0data				
30	IDC2CLK	idc1clk		norspi_dq[2]	norspi_en[2]	
31	IDC2DATA	idc1data		norspi_dq[3]	norspi_en[3]	
32	IDC3CLK	idc2clk	vin_strig0			
33	IDC3DATA	idc2data	vin_strig1			
34	IR_IN	ir_in				
35	SSI0CLK	ssi0_sclk	norspi_clk	uart2_ahb_rx	ssis_sclk	
36	SSI0MOSI	ssi0_txd	norspi_dq[0]	uart2_ahb_tx	ssis_rxd	
37	SSI0MISO	ssi0_rxd	norspi_dq[1]	uart2_ahb_cts_n	ssis_txd	
38	SSI0ENO	ssi0_en0	norspi_en[0]	uart2_ahb_rts_n	ssis_en	
39	SSI0EN1	ssi0_en1	norspi_en[1]			
40	SSI2CLK	ssi2_sclk	idc3clk			
41	SSI2MOSI	ssi2_txd	idc3data			
42	SSI2MISO	ssi2_rxd				
43	SSI2ENO	ssi2_en0				
44	SSI2EN1	ssi2_en1				
45	UART0RX	uart0rx	uart2_ahb_rx			
46	UART0TX	uart0tx	uart2_ahb_tx			
47	UART1RX	uart1_ahb_rx				
48	UART1TX	uart1_ahb_tx				
49	UART1CTSN	uart1_ahb_cts_n				
50	UART1RTSN	uart1_ahb_rts_n				
51	I2S_CLK	i2s_clk	dmic_clk			

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
52	I2S_SI	i2s_si	dmic_dat			
53	I2S_SO	i2s_so				
54	I2S_WS	i2s_ws				
55	CLK_AU	clk_au				
56	ENET_TXEN	enet_txen	sc_a0	enet_txen	ssi1_txd	norspi_en[0]
57	ENET_TXD_0	enet_txd_0	sc_a1	enet_txd_0	ssi1_en0	norspi_en[1]
58	ENET_TXD_1	enet_txd_1	sc_a2	enet_txd_1	ssi1_en1	norspi_en[2]
59	ENET_TXD_2		sc_a3	enet_txd_2	ssi1_en2	
60	ENET_TXD_3		sc_b0	enet_txd_3	ssi1_en3	
61	ENET_RXD_0	enet_rxd_0	sc_b1	enet_rxd_0	ssi1_rxd	norspi_dq[0]
62	ENET_RXD_1	enet_rxd_1	sc_b2	enet_rxd_1		norspi_dq[1]
63	ENET_RXD_2		sc_b3	enet_rxd_2		norspi_dq[2]
64	ENET_RXD_3			enet_rxd_3		norspi_dq[3]
65	ENET_RXDV	enet_rxdv		enet_rxdv		
66	ENET_MDC	enet_mdc		enet_mdc		
67	ENET_MDIO	enet_mdio		enet_mdio		
68	ENET_CLK_TX	enet_2nd_ref_clk		enet_clk_tx		
69	ENET_CLK_RX	enet_ref_clk		enet_clk_rx		
70	ENET_GTX_CLK	enet_gtx_clk		enet_gtx_clk		
71	ENET_EXT_OSC_CLK			enet_ext_osc_clk		
72	WP		nand_wp			
73	SMIO_0		nand_ce	norspi_clk		
74	SMIO_1		nand_rb	norspi_dq[4]		
75	SMIO_2		sd_clk			
76	SMIO_3		sd_cmd			
77	SMIO_4		sd_cd			
78	SMIO_5		sd_wp			
79	SMIO_6		nand_re	norspi_dq[5]		
80	SMIO_7		nand_we	norspi_dq[6]		
81	SMIO_8		nand_ale	norspi_dq[7]		
82	SMIO_9		nand_d[0]	norspi_en[0]		
83	SMIO_10		nand_d[1]	norspi_en[1]		
84	SMIO_11		nand_d[2]	norspi_en[2]		
85	SMIO_12		nand_d[3]	norspi_en[3]		
86	SMIO_13		nand_d[4]	norspi_dq[0]		
87	SMIO_14		nand_d[5]	norspi_dq[1]		
88	SMIO_15		nand_d[6]	norspi_dq[2]		

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
89	SMIO_16		nand_d[7]	norspi_dq[3]		
90	SMIO_17		nand_cle			
91	SMIO_18		sd_d[0]			
92	SMIO_19		sd_d[1]			
93	SMIO_20		sd_d[2]			
94	SMIO_21		sd_d[3]			
95	SMIO_22		sd_d[4]		sc_c0	ssis_sclk
96	SMIO_23		sd_d[5]		sc_c1	ssis_rxd
97	SMIO_24		sd_d[6]		sc_c2	ssis_txd
98	SMIO_25		sd_d[7]		sc_c3	ssis_en
99	SMIO_26		sdxc_clk			
100	SMIO_27		sdxc_cmd			
101	SMIO_28		sdxc_d[0]		sc_d0	ssis_sclk
102	SMIO_29		sdxc_d[1]		sc_d1	ssis_rxd
103	SMIO_30		sdxc_d[2]		sc_d2	ssis_txd
104	SMIO_31		sdxc_d[3]		sc_d3	ssis_en
105	SMIO_32		sdxc_cd			
106	SMIO_33		sdxc_wp			
107	SMIO_34		sdxc_d[4]			
108	SMIO_35		sdxc_d[5]			
109	SMIO_36		sdxc_d[6]			
110	SMIO_37		sdxc_d[7]			
111	SMIO_38		sd_reset			
112	SMIO_39		sdxc_reset			
113	HPD	hdmitx_hpd				
114	CEC	hdmitx_cec				
115	SVSYNC	vin_svsync	idsp_pip_iopad_ master_hsync			
116	SHSYNC	vin_shsync	idsp_pip_iopad_ master_vsync			
117	SENSOR_RST					
118	VDO_OUT_0	vd0_out[0]				
119	VDO_OUT_1	vd0_out[1]				
120	VDO_OUT_2	vd0_out[2]				
121	VDO_OUT_3	vd0_out[3]				
122	VDO_OUT_4	vd0_out[4]				
123	VDO_OUT_5	vd0_out[5]				
124	VDO_OUT_6	vd0_out[6]				
125	VDO_OUT_7	vd0_out[7]				
126	VDO_OUT_8	vd0_out[8]				
127	VDO_OUT_9	vd0_out[9]				

GPIO	Pin Name	Multiplexed Function				
		First	Second	Third	Fourth	Fifth
128	VDO_OUT_10	vd0_out[10]				
129	VDO_OUT_11	vd0_out[11]				
130	VDO_OUT_12	vd0_out[12]				
131	VDO_OUT_13	vd0_out[13]				
132	VDO_OUT_14	vd0_out[14]				
133	VDO_OUT_15	vd0_out[15]				
134	VDO_CLK	vd0_clk				
135	VDO_VSYNC	vd0_vsync				
136	VDO_HSYNC	vd0_hsync				
137	VDO_HVLD	vd0_hvld				
138	VD_PWM	pwm_0				

Table 4-13. Fail-Safe Pins Which Can Have Active Signals At or Below 3.6 V When the H22S75 is Powered Down.

4.5 Electrical: Video Signal Wave Forms and Timing

4.5.1 Video Waveform: Video Input (VIN) LVCMOS Timing

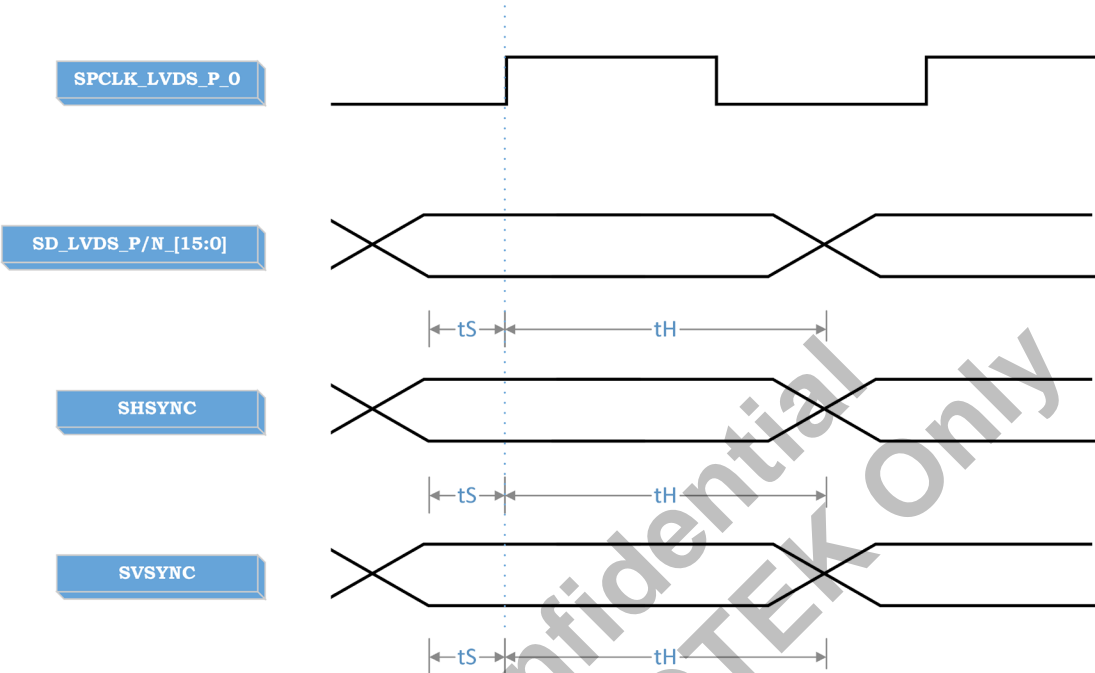


Figure 4-1. Video Input (VIN) LVCMOS Timing.

Parameter	Setup (tS)	Hold (tH)	Comment
Data: SD_LVDS_P/N_[16:0]	2 ns	2 ns	Assume the rising edge of the pixel clock SPCLK_LVDS_P_0 is used to latch the data.
HSync: SHSYNC	2 ns	2 ns	
VSyn: SVSYNC	2 ns	2 ns	
SField: (See Section 2.3)	2 ns	2 ns	

Table 4-14. LVCMOS Video Input Timing Setup/Hold With Respect to **SPCLK_LVDS_P/N_[N]**.

4.5.2 Video Waveform: Video Input (VIN) SLVS Timing

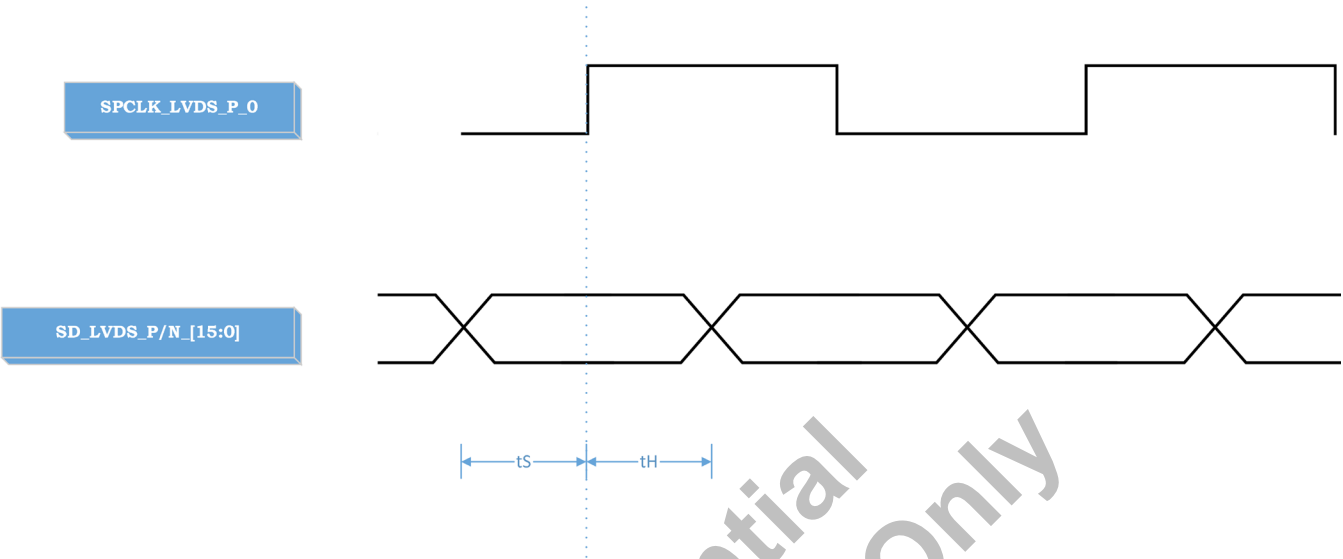


Figure 4-2. Video Input (VIN) SLVS Timing.

Parameter	Setup (tS)	Hold (tH)	Comment
Data: SD_LVDS_P/N_[16:0]	150 ps	150 ps	Assume the rising edge of the pixel clock SPCLK_LVDS_P_0 is used to latch the data.

Table 4-15. SLVS Video Input Timing Setup/Hold With Respect to **SPCLK_LVDS_P/N_[N]**.

4.5.3 Video Waveform: Video Output (VOUT) Timing

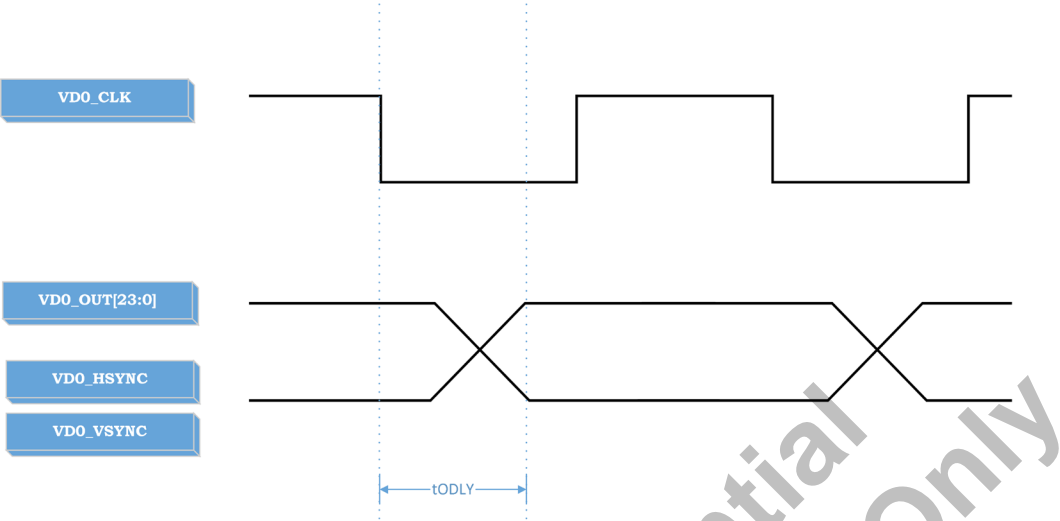


Figure 4-3. Video Output Timing.

Parameter	Minimum	Typical	Maximum	Comment
VDO_CLK Frequency		Resolution Dependent		Assume the data is latched out at the falling edge of VDO_CLK .
VDO_CLK Duty	40%	50%	60%	
tODLY Output Delay	-2 ns		2 ns	

Table 4-16. Video Output Timing Setup/Hold With Respect to **VDO_CLK**.

4.6 Electrical: SD Controller Timing

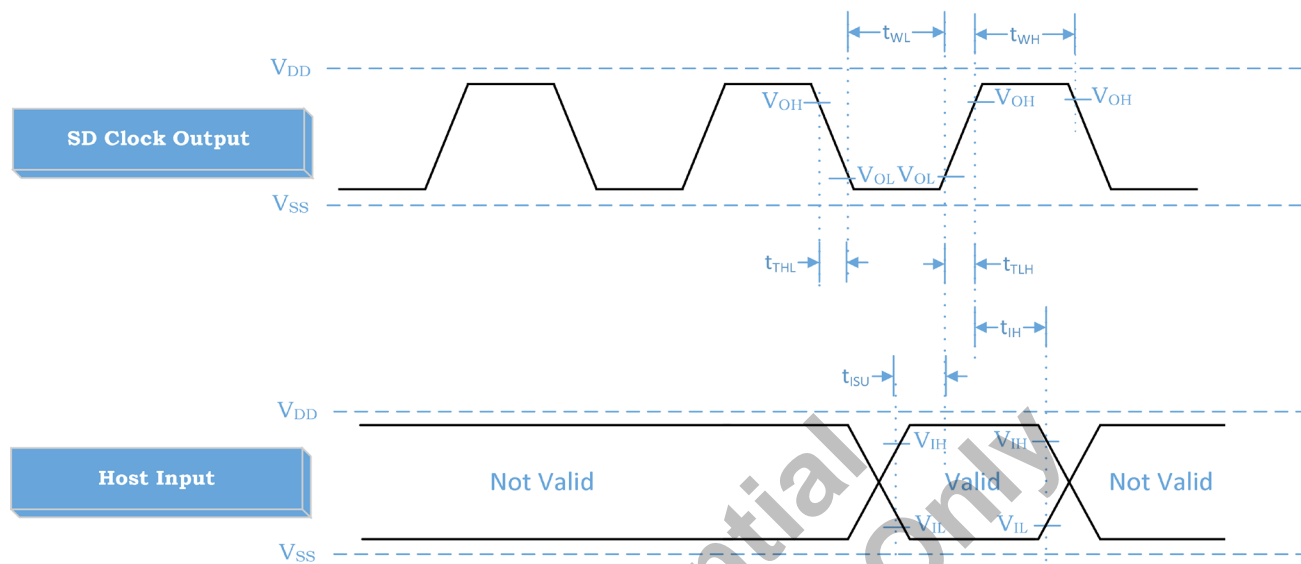


Figure 4-4. SD Host Input Timing.

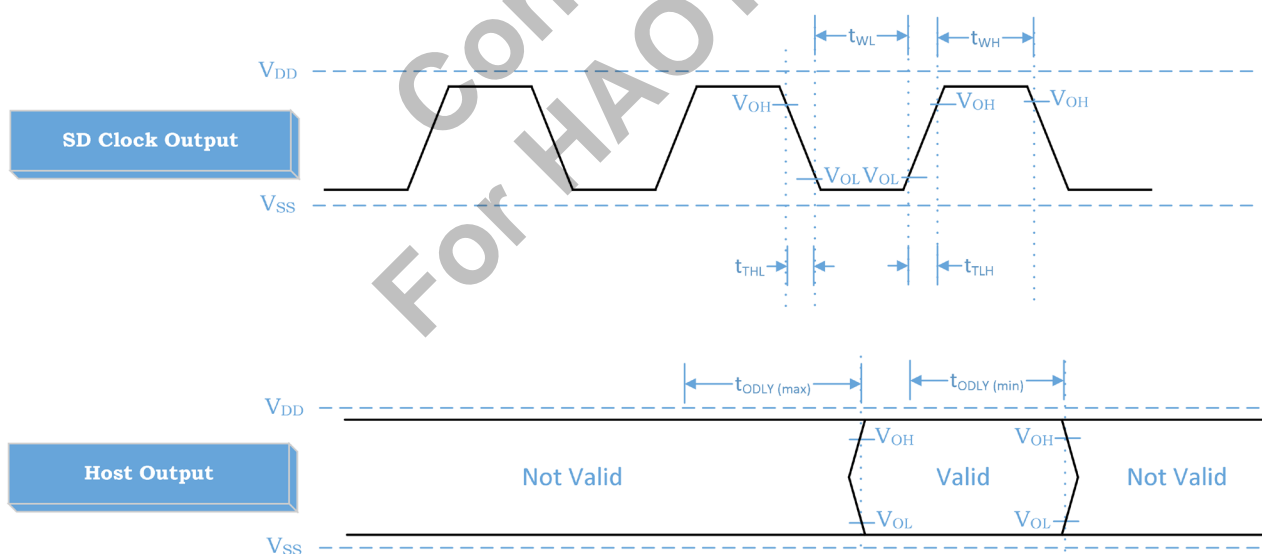


Figure 4-5. SD Host Output Timing.

Parameter	Symbol	Min	Max	Unit	Comment
Clock CLK: All values are referred to as min (VIH) and max (VIL)					
Clock Frequency: Data Transfer Mode	f_{PP}	0	48	MHz	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Clock Frequency: Identification Mode	f_{OD}	0/100	400	kHz	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Clock Low Time	t_{WL}	7		ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Clock High Time	t_{WH}	7		ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Clock Rise Time	t_{TLH}		3	ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Clock Fall Time	t_{THL}		3	ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Inputs CMD, DAT: Referenced to CLK					
Input Set-Up Time	t_{ISU}	6		ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Input Hold Time	t_{IH}	1.5		ns	$C_{CARD} \leq 10 \text{ pF}$ (1 Card)
Outputs CMD, DAT: Referenced to CLK at 48 MHz					
Output Delay Time	t_{ODLY}	8.5	12.5	ns	$C_L \leq 40 \text{ pF}$ (1 Card)

Table 4-17. SD Controller Timing Parameters.

4.7 Electrical: eMMC Boot Timing

To successfully boot from eMMC, the eMMC device should return boot data with the following timing constraints.

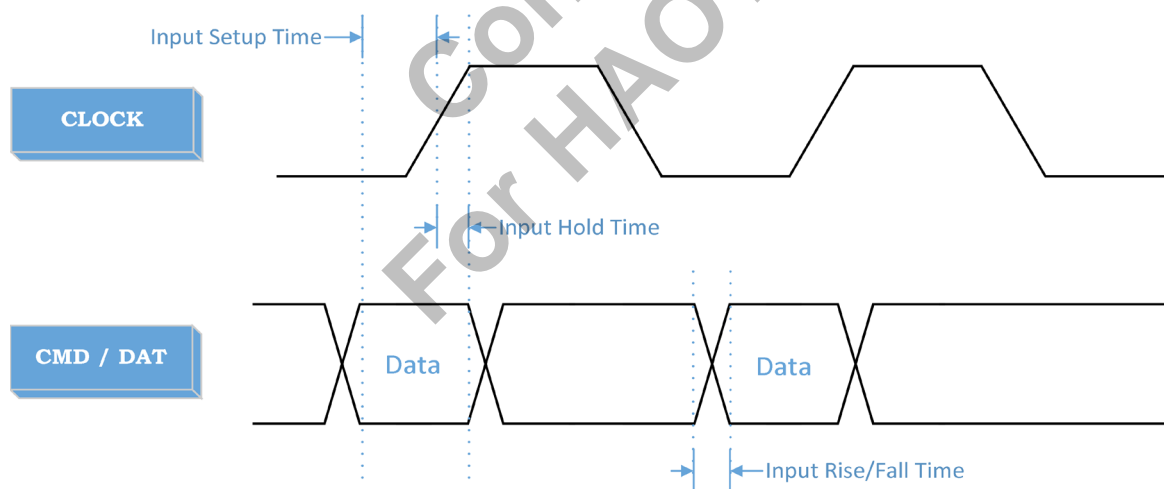


Figure 4-6. eMMC Boot Timing Diagram.

Parameter	Minimum	Maximum
Host CMD / DAT Input Timing		
Input Setup Time	6 ns	
Input Hold Time	1.5 ns	
Signal Rise Time		3 ns
Signal Fall Time		3 ns

Table 4-18. eMMC Boot Timing.

Note:

1. CMD / DAT input rise and fall time are measured by VIL and VIH.

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5. PACKAGE

The H22S75 chip has a 369-pin WFBGA package (14 mm x 14 mm).

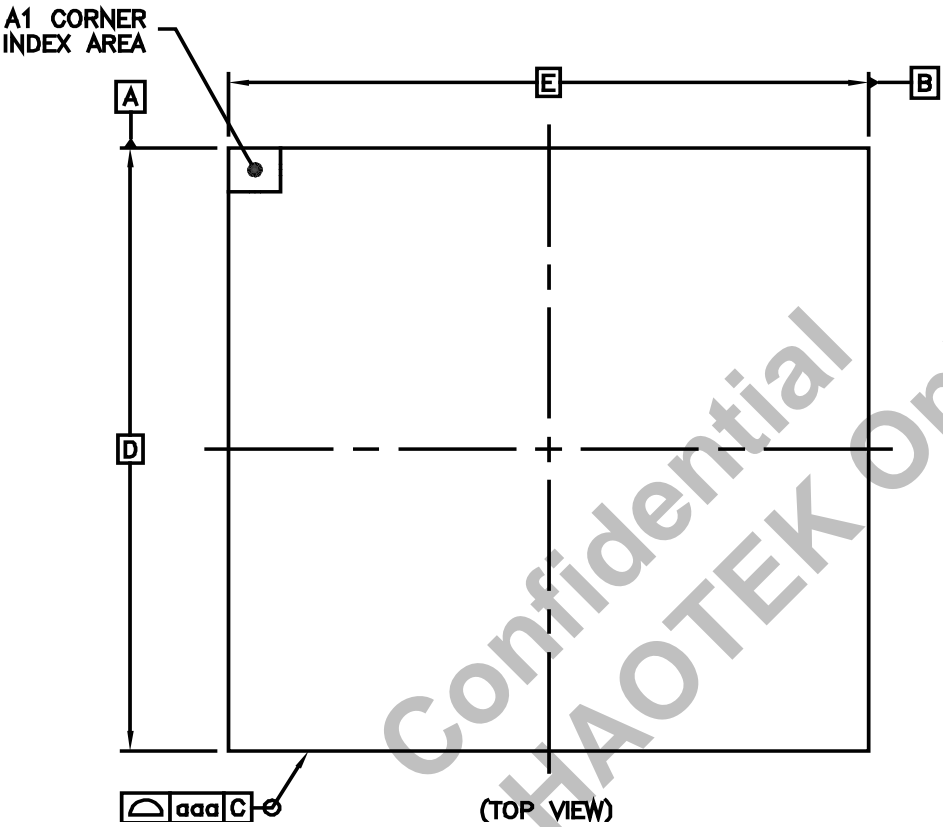


Figure 5-1. Top View of the H22S75 Package.

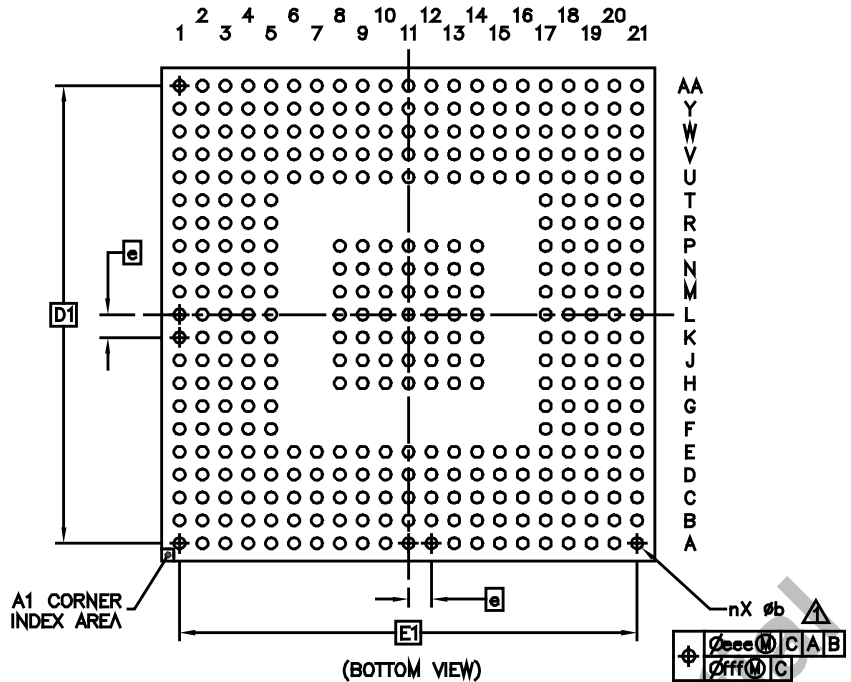


Figure 5-2. Bottom View of the H22S75 Package.

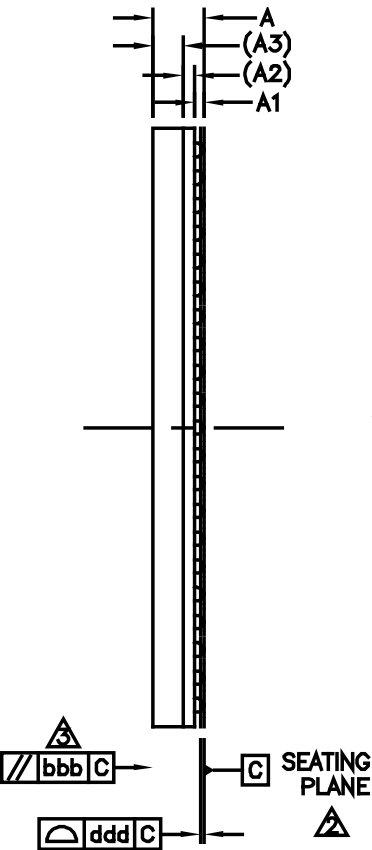


Figure 5-3. Side View of the H22S75 Package.

Description	Symbol	Minimum	Nominal	Maximum
Total Thickness	A			1.3
Stand Off	A1	0.16		0.26
Substrate Thickness	A2		0.24 REF	
Mold Thickness	A3		0.7 REF	
Body Size	D		14 BSC	
	E		14 BSC	
Ball Diameter			0.3	
Ball Opening			0.275	
Ball Width	b	0.27		0.37
Ball Pitch	e		0.65 BSC	
Ball Count	n		369	
Edge Ball Center to Center	D1		13 BSC	
	E1		13 BSC	
Body Center to Contact Ball	SD			
	SE			
Package Edge Tolerance	aaa		0.1	
Mold Flatness	bbb		0.2	
Coplanarity	ddd		0.08	
Ball Offset (Package)	eee		0.15	
Ball Offset (Ball)	fff		0.08	

Table 5-1. Dimensions of the H22S75 Package (millimeters).

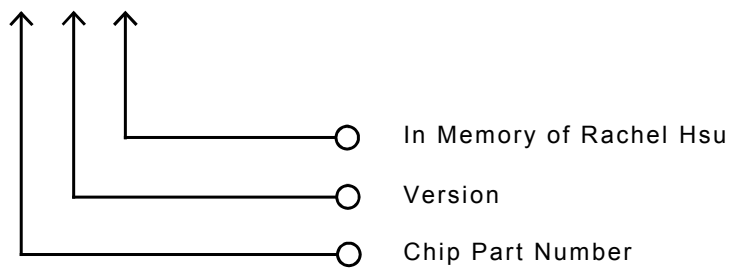
Notes for table and figures:

1. All dimensions are in millimeters.
2. Dimension b is measured at the maximum solder ball diameter, parallel to Datum Plane C.
3. Datum C (Seating Plane) is defined by the spherical crowns of the solder balls.
4. Parallelism measurement excludes any effect of mark on top surface of the package.
5. Dimension and Tolerances: ASME Y14.5M

6. CONTACT AND ORDER INFORMATION

All chips in the H22S75 series are Lead-Free, Halogen-Free and RoHS compliant.

H22S75-A0-RH



For complete Ambarella contact information, please visit www.ambarella.com.

7. PIN LIST AND MAPPING TABLE

This section provides a list of the 369 external pins according to their location on the H22S75 chip. Figure 7-1 below indicates the orientation of the pins by column (numbers) and row (letters).

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21		
A	ddr_dq_30	ddr_dq_23	ddr_dq_21	ddr_calibr	ddr_vref	spclk_l_vds_p	sd_lvsd_p4	sd_lvsd_p5	sd_lvsd_p6	sd_lvsd_p7	spclk_l_vds_p	sd_lvsd_p0	sd_lvsd_p1	sd_lvsd_p2	sd_lvsd_p3	usb_dp_vdd33	xin	xo_rtc	pwc_wkup	pwc_ps_eq1	hdmi_a_vdd18	A	
B	ddr_dq_28	ddr_dq_31	ddr_dm_2	ddr_dq_22	ddr_cs	spclk_l_vds_n	sd_lvsd_n4	sd_lvsd_n5	sd_lvsd_n6	sd_lvsd_n7	spclk_l_vds_n	sd_lvsd_n0	sd_lvsd_n1	sd_lvsd_n2	sd_lvsd_n3	usb_d_m	xout	xi_rtc	pwc_ps_eq3	pwc_rs_tinb	hdmi_a_vdd18	B	
C	ddr_dq_s3	ddr_dq_29	ddr_dq_s2	ddr_dq_20	ddr_cs_2	VSSI	dac_rs_et	dac_vrefin	dac_comp	VSSI	VSSI	VSSI	avss	avss	VSSI	VSSI	usb_rext	pwc_pseq2	ir_in	hdmi_c_h2m	hdmi_c_h2p	C	
D	ddr_dq_s_bar	ddr_dm_3	ddr_dm_s_bar	ddr_dq_16	ddr_ad_5	dac_io	svsync	shsync	VSSI	VSSI	VSSI	avdd18	avdd	mipi_ana_avd	avdd18	dvdd	detect_vbus	pwc_avdd33	pwc_rstob	hdmi_c_h1m	hdmi_c_h1p	D	
E	ddr_dq_26	ddr_dq_25	ddr_dq_17	ddr_dq_18	ddr_ad_2	ddr_vddq_cke	adc_ch1	adc_ch2	adc_ch3	VSSI	VSSI	VSSI	VSSI	VSSI	VSSI	VSSI	avdd33	sdxc_vddo	pwc_avdd18	hpd	hdmi_c_h0m	hdmi_c_h0p	E
F	ddr_dq_24	ddr_dq_27	ddr_dq_19	ddr_ad_3	ddr_vddq												vddp	VSSI	cec	hdmi_c_lkm	hdmi_c_lkp	F	
G	ddr_ad_13	ddr_ad_12	ddr_ad_11	ddr_ad_10	ddr_vddq												vddo	smio_3_6	smio_3_7	smio_3_9	hdmi_ext		G
H	ddr_ck_2_bar	ddr_ck_2	ddr_ad_11	ddr_we	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	VSSI				nand_vddo	smio_3_5	smio_3_4	smio_3_3	smio_3_2		H
J	ddr_ck_e_2	ddr_ck_1	ddr_ad_6	ddr_ad_8	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	VSSI				smio_2_0	smio_2_8	smio_2_9	smio_2_0	smio_3_1		J
K	ddr_ck_bar	ddr_ck	ddr_ad_14	ddr_ad_10	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	sd_vddo				smio_2_1	smio_2_7	smio_2_6	smio_2_3	smio_2_9		K
L	ddr_ck_e	ddr_ad_15	ddr_ad_1	ddr_odt	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	sd_vddo				smio_2_5	smio_2_4	smio_2_8	smio_2_1	smio_2_2		L
M	ddr_dq_14	ddr_dq_7	ddr_dq_5	ddr_ra_s	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	VSSI				smio_3_8	smio_3_3	smio_3_5	smio_4	wp		M
N	ddr_dq_12	ddr_dq_13	ddr_dq_s_bar	ddr_ca_s	ddr_vddq		VSSI	VDDI	VSSI	VDDI	VSSI	VDDI	VSSI				smio_1_3	smio_1_4	smio_1_5	smio_1_6	smio_1_7		N
P	ddr_dq_s_bar	ddr_dq_15	ddr_dq_s_0	ddr_ad_6	ddr_ad_7		vddp	VDDI	VSSI	vddo	vddo	vddo	VSSI				smio_1_2	smio_1_1	smio_1_0	smio_9	smio_7		P
R	ddr_dq_s_1	ddr_dm_1	ddr_dm_0	ddr_ad_4	ddr_ad_9												ssi0en_0	smio_1	smio_0	smio_6	smio_8		R
T	ddr_dq_10	ddr_dq_11	ddr_dq_3	ddr_dq_2	ddr_ba_0												ssi0en_1	sc_d0	sc_c0	sc_b0	sc_a0		T
U	ddr_dq_8	ddr_dq_9	ddr_dq_1	ddr_dq_0	ddr_ba_2	clk_si	vd0_out_8	vd0_hsync	enet_md	enet_clk_rx	por_l	i2s_clk	jtag_tdi	idcdata	gpio_4	uart1cts_n	uart1rts_n	sc_d1	sc_c1	sc_b1	sc_a1		U
V	vd0_out_14	vd0_out_15	vd0_out_10	vd0_clk	ddr_res	clk_si2	vd0_out_7	enet_mdio	enet_clk_tx	test_mode	i2s_si	jtag_tms	idc2clk	gpio_5	gpio_0	gpio_1	sc_d2	sc_d3	sc_c2	sc_b2	sc_a2		V
W	vd0_out_4	vd0_out_6	vd0_out_1	vd0_out_11	ddr_vref	vd0_out_0	vd0_hvld	enet_tx_d0	enet_tx_en	enet_rx_d2	enet_rx_d3	i2s_so	jtag_clk	idc2data	gpio_6	gpio_2	uart1rx	timer1	sc_c3	sc_b3	sc_a3		W
Y	ssi2en_1	ssi2mi_1	vd0_out_5	vd_pw_m	vd0_out_2	vd0_out_12	vd0_vsync	enet_tx_d1	enet_tx_clk	enet_rx_d1	enet_rx_dv	i2s_ws	jtag_tdo	idc3clk	gpio_7	gpio_3	uart1tx	ssi0mi_so	fsource_0	vddwl_0	sc_e0		Y
AA	ssi2en_0	ssi2mo_si	sensor_rst	ssi2clk	vd0_out_3	vd0_out_13	vd0_out_9	enet_tx_d2	enet_tx_d3	enet_rx_d0	enet_ext_osc	clk_au	jtag_rst_l	idc3data	idccclk	uart0tx	uart0rx	ssi0mo_si	ssi0clk	timer2	timer0		AA
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21		

Figure 7-1. Pin Map for the H22S75 Chip.

The table below lists all of the external pins on the H22S75 chip in alphabetic order by map location. Each entry provides the pin name as it appears on the ball map, the location of the pin on the map and on schematics, the functional group, and multiplexed functionality detail if applicable.

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
A1	DDR_DQ_30	DDR	SSTL						
A2	DDR_DQ_23	DDR	SSTL						
A3	DDR_DQ_21	DDR	SSTL						
A4	DDR_CAL-IBR	DDR	SSTL						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
A5	DDR_VREF_2	DDR	SSTL						
A6	SPCLK_LVDS_P_1	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A7	SD_LVDS_P_4	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A8	SD_LVDS_P_5	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A9	SD_LVDS_P_6	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A10	SD_LVDS_P_7	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A11	SPCLK_LVDS_P_0	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A12	SD_LVDS_P_0	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A13	SD_LVDS_P_1	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
A14	SD_LVDS_P_2	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A15	SD_LVDS_P_3	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
A16	USB_DP	USB	Analog						
A17	XIN	Global	XOSC						
A18	XO_RTC	RTC	Analog						
A19	PWC_WKUP	PWC	Analog						
A20	PWC_PSEQ1	PWC	Analog						
A21	HDMI_AVDD33_ESD	HDMI	Analog Supply						
B1	DDR_DQ_28	DDR	SSTL						
B2	DDR_DQ_31	DDR	SSTL						
B3	DDR_DM_2	DDR	SSTL						
B4	DDR_DQ_22	DDR	SSTL						
B5	DDR_CS	DDR	SSTL						
B6	SPCLK_LVDS_N_1	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B7	SD_LVDS_N_4	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B8	SD_LVDS_N_5	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B9	SD_LVDS_N_6	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
B10	SD_LVDS_N_7	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B11	SPCLK_LVDS_N_0	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B12	SD_LVDS_N_0	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B13	SD_LVDS_N_1	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B14	SD_LVDS_N_2	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B15	SD_LVDS_N_3	Sensor	Sub_LVDS / SLVS / LVC-MOS / MIPI						
B16	USB_DM	USB	Analog						
B17	XOUT	Global	XOSC						
B18	XI_RTC	RTC	Analog						
B19	PWC_PSEQ3	PWC	Analog						
B20	PWC_RST-INB	PWC	Analog						
B21	HDMI_AVDD18_ESD	HDMI	Analog Supply						
C1	DDR_DQS_3	DDR	SSTL						
C2	DDR_DQ_29	DDR	SSTL						
C3	DDR_DQS_2	DDR	SSTL						
C4	DDR_DQ_20	DDR	SSTL						
C5	DDR_CS_2	DDR	SSTL						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
C6	VSSI	Power	Ground						
C7	DAC_RSET	DAC	Analog						
C8	DAC_VREFIN	DAC	Analog						
C9	DAC_COMP	DAC	Analog						
C10	VSSI	Power	Ground						
C11	VSSI	Power	Ground						
C12	VSSI	Power	Ground						
C13	AVSS	Power	Ground						
C14	AVSS	Power	Ground						
C15	VSSI	Power	Ground						
C16	VSSI	Power	Ground						
C17	USB_REXT	USB	Analog						
C18	PWC_PSEQ2	PWC	Analog						
C19	IR_IN	IR	CMOS	ir_in					34
C20	HDMI_CH2_M	HDMI	Analog						
C21	HDMI_CH2_P	HDMI	Analog						
D1	DDR_DQS_BAR_3	DDR	SSTL						
D2	DDR_DM_3	DDR	SSTL						
D3	DDR_DQS_BAR_2	DDR	SSTL						
D4	DDR_DQ_16	DDR	SSTL						
D5	DDR_ADDR_5	DDR	SSTL						
D6	DAC_IO	DAC	Analog						
D7	SVSYNC	Sensor	CMOS	vin_svsync	idsp_pip_iopad_master_hsync				115
D8	SHSYNC	Sensor	CMOS	vin_shsync	idsp_pip_iopad_master_vsync				116
D9	VSSI	Power	Ground						
D10	VSSI	Power	Ground						
D11	VSSI	Power	Ground						
D12	AVDD18	Power	Analog Supply						
D13	AVDD	Power	Analog Supply						
D14	MIPI_ANA_AVDD18_IO	Power	Analog Supply						
D15	AVDD18	Power	Analog Supply						
D16	DVDD	Power	Digital Supply						
D17	DETECT_VBUS	USB	CMOS						
D18	PWC_AVDD33	PWC	Analog						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
D19	PWC_RSTOB	PWC	Analog						
D20	HDMI_CH1_M	HDMI	Analog						
D21	HDMI_CH1_P	HDMI	Analog						
E1	DDR_DQ_26	DDR	SSTL						
E2	DDR_DQ_25	DDR	SSTL						
E3	DDR_DQ_17	DDR	SSTL						
E4	DDR_DQ_18	DDR	SSTL						
E5	DDR_ADDR_2	DDR	SSTL						
E6	DDR_VDDQ_CKE	Power	DDR HOST Supply						
E7	ADC_CH_1	ADC	Analog						
E8	ADC_CH_2	ADC	Analog						
E9	ADC_CH_3	ADC	Analog						
E10	VSSI	Power	Ground						
E11	VSSI	Power	Ground						
E12	VSSI	Power	Ground						
E13	VSSI	Power	Ground						
E14	VSSI	Power	Ground						
E15	VSSI	Power	Ground						
E16	AVDD33	Power	Analog Supply						
E17	SDXC_VDDO	Power	IO Power						
E18	PWC_AVDD18	PWC	Analog Supply						
E19	HPD	GPIO	CMOS	hdmix_hpd					113
E20	HDMI_CH0_M	HDMI	Analog						
E21	HDMI_CH0_P	HDMI	Analog						
F1	DDR_DQ_24	DDR	SSTL						
F2	DDR_DQ_27	DDR	SSTL						
F3	DDR_DQ_19	DDR	SSTL						
F4	DDR_ADDR_3	DDR	SSTL						
F5	DDR_VDDQ	Power	DDR HOST Supply						
F17	VDDP	Power	Pre-driver Supply						
F18	VSSI	Power	Ground						
F19	CEC	HDMI	CMOS	hdmix_cec					114
F20	HDMI_CLK_M	HDMI	Analog						
F21	HDMI_CLK_P	HDMI	Analog						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
G1	DDR_ADDR_13	DDR	SSTL						
G2	DDR_ADDR_12	DDR	SSTL						
G3	DDR_ADDR_4	DDR	SSTL						
G4	DDR_ADDR_0	DDR	SSTL						
G5	DDR_VDDQ	Power	DDR HOST Supply						
G17	VDDO	Power	IO Power						
G18	SMIO_36	SMIO	CMOS		sdxc_d[6]				109
G19	SMIO_37	SMIO	CMOS		sdxc_d[7]				110
G20	SMIO_39	SMIO	CMOS		sdxc_reset				112
G21	HDMI_REXT	HDMI	Analog						
H1	DDR_CK_2_BAR	DDR	SSTL						
H2	DDR_CK_2	DDR	SSTL						
H3	DDR_ADDR_11	DDR	SSTL						
H4	DDR_WE	DDR	SSTL						
H5	DDR_VDDQ	Power	DDR HOST Supply						
H8	VSSI	Power	Ground						
H9	VDDI	Power	Digital Supply						
H10	VSSI	Power	Ground						
H11	VDDI	Power	Digital Supply						
H12	VSSI	Power	Ground						
H13	VDDI	Power	Digital Supply						
H14	VSSI	Power	Ground						
H17	NAND_VDDO								
H18	SMIO_35	SMIO	CMOS		sdxc_d[5]				108
H19	SMIO_34	SMIO	CMOS		sdxc_d[4]				107
H20	SMIO_33	SMIO	CMOS		sdxc_wp				106
H21	SMIO_32	SMIO	CMOS		sdxc_cd				105
J1	DDR_CKE_2	DDR	SSTL						
J2	DDR_BA_1	DDR	SSTL						
J3	DDR_ADDR_6	DDR	SSTL						
J4	DDR_ADDR_8	DDR	SSTL						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
J5	DDR_VDDQ	Power	DDR HOST Supply						
J8	VSSI	Power	Ground						
J9	VDDI	Power	Digital Supply						
J10	VSSI	Power	Ground						
J11	VDDI	Power	Digital Supply						
J12	VSSI	Power	Ground						
J13	VDDI	Power	Digital Supply						
J14	VSSI	Power	Ground						
J17	SMIO_20	SMIO	CMOS		sd_d[2]				93
J18	SMIO_28	SMIO	CMOS		sdxc_d[0]		sc_d0	ssis_sclk	101
J19	SMIO_29	SMIO	CMOS		sdxc_d[1]		sc_d1	ssis_rxd	102
J20	SMIO_30	SMIO	CMOS		sdxc_d[2]		sc_d2	ssis_txd	103
J21	SMIO_31	SMIO	CMOS		sdxc_d[3]		sc_d3	ssis_en	104
K1	DDR_CK_BAR	DDR	SSTL						
K2	DDR_CK	DDR	SSTL						
K3	DDR_ADDR_14	DDR	SSTL						
K4	DDR_ADDR_10	DDR	SSTL						
K5	DDR_VDDQ	Power	DDR HOST Supply						
K8	VSSI	Power	Ground						
K9	VDDI	Power	Digital Supply						
K10	VSSI	Power	Ground						
K11	VDDI	Power	Digital Supply						
K12	VSSI	Power	Ground						
K13	VDDI	Power	Digital Supply						
K14	SD_VDDO	Power	IO Power						
K17	SMIO_21	SMIO	CMOS		sd_d[3]				94
K18	SMIO_27	SMIO	CMOS		sdxc_cmd				100
K19	SMIO_26	SMIO	CMOS		sdxc_clk				99
K20	SMIO_23	SMIO	CMOS		sd_d[5]		sc_c1	ssis_rxd	96
K21	SMIO_19	SMIO	CMOS		sd_d[1]				92
L1	DDR_CKE	DDR	SSTL						
L2	DDR_ADDR_15	DDR	SSTL						
L3	DDR_ADDR_1	DDR	SSTL						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
L4	DDR_ODT	DDR	SSTL						
L5	DDR_VDDQ	Power	DDR HOST Supply						
L8	VSSI	Power	Ground						
L9	VDDI	Power	Digital Supply						
L10	VSSI	Power	Ground						
L11	VDDI	Power	Digital Supply						
L12	VSSI	Power	Ground						
L13	VDDI	Power	Digital Supply						
L14	SD_VDDO	Power	IO Power						
L17	SMIO_25	SMIO	CMOS		sd_d[7]		sc_c3	ssis_en	98
L18	SMIO_24	SMIO	CMOS		sd_d[6]		sc_c2	ssis_txd	97
L19	SMIO_2	SMIO	CMOS		sd_clk				75
L20	SMIO_18	SMIO	CMOS		sd_d[0]				91
L21	SMIO_22	SMIO	CMOS		sd_d[4]		sc_c0	ssis_sclk	95
M1	DDR_DQ_14	DDR	SSTL						
M2	DDR_DQ_7	DDR	SSTL						
M3	DDR_DQ_5	DDR	SSTL						
M4	DDR_RAS	DDR	SSTL						
M5	DDR_VDDQ	Power	DDR HOST Supply						
M8	VSSI	Power	Ground						
M9	VDDI	Power	Digital Supply						
M10	VSSI	Power	Ground						
M11	VDDI	Power	Digital Supply						
M12	VSSI	Power	Ground						
M13	VDDI	Power	Digital Supply						
M14	VSSI	Power	Ground						
M17	SMIO_38	SMIO	CMOS		sd_reset				111
M18	SMIO_3	SMIO	CMOS		sd_cmd				76
M19	SMIO_5	SMIO	CMOS		sd_wp				78
M20	SMIO_4	SMIO	CMOS		sd_cd				77
M21	WP	GPIO	CMOS		nand_wp				72
N1	DDR_DQ_12	DDR	SSTL						
N2	DDR_DQ_13	DDR	SSTL						
N3	DDR_DQS_ BAR_0	DDR	SSTL						
N4	DDR_CAS	DDR	SSTL						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
N5	DDR_VDDQ	Power	DDR HOST Supply						
N8	VSSI	Power	Ground						
N9	VDDI	Power	Digital Supply						
N10	VSSI	Power	Ground						
N11	VDDI	Power	Digital Supply						
N12	VSSI	Power	Ground						
N13	VDDI	Power	Digital Supply						
N14	VSSI	Power	Ground						
N17	SMIO_13	SMIO	CMOS		nand_d[4]	norspi_dq[0]			86
N18	SMIO_14	SMIO	CMOS		nand_d[5]	norspi_dq[1]			87
N19	SMIO_15	SMIO	CMOS		nand_d[6]	norspi_dq[2]			88
N20	SMIO_16	SMIO	CMOS		nand_d[7]	norspi_dq[3]			89
N21	SMIO_17	SMIO	CMOS		nand_cle				90
P1	DDR_DQS_BAR_1	DDR	SSTL						
P2	DDR_DQ_15	DDR	SSTL						
P3	DDR_DQS_0	DDR	SSTL						
P4	DDR_DQ_6	DDR	SSTL						
P5	DDR_ADDR_7	DDR	SSTL						
P8	VDDP	Power	Pre-driver Supply						
P9	VDDI	Power	Digital Supply						
P10	VSSI	Power	Ground						
P11	VDDO	Power	IO Power						
P12	VDDO	Power	IO Power						
P13	VDDO	Power	IO Power						
P14	VSSI	Power	Ground						
P17	SMIO_12	SMIO	CMOS		nand_d[3]	norspi_en[3]			85
P18	SMIO_11	SMIO	CMOS		nand_d[2]	norspi_en[2]			84
P19	SMIO_10	SMIO	CMOS		nand_d[1]	norspi_en[1]			83

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
P20	SMIO_9	SMIO	CMOS		nand_d[0]	norspi_en[0]			82
P21	SMIO_7	SMIO	CMOS		nand_we	norspi_dq[6]			80
R1	DDR_DQS_1	DDR	SSTL						
R2	DDR_DM_1	DDR	SSTL						
R3	DDR_DM_0	DDR	SSTL						
R4	DDR_DQ_4	DDR	SSTL						
R5	DDR_ADDR_9	DDR	SSTL						
R17	SSIOEN0	GPIO	CMOS	ssi0_en0	norspi_en[0]	uart2_ahb_rts_n	ssis_en		38
R18	SMIO_1	SMIO	CMOS		nand_rb	norspi_dq[4]			74
R19	SMIO_0	SMIO	CMOS		nand_ce	norspi_clk			73
R20	SMIO_6	SMIO	CMOS		nand_re	norspi_dq[5]			79
R21	SMIO_8	SMIO	CMOS		nand_ale	norspi_dq[7]			81
T1	DDR_DQ_10	DDR	SSTL						
T2	DDR_DQ_11	DDR	SSTL						
T3	DDR_DQ_3	DDR	SSTL						
T4	DDR_DQ_2	DDR	SSTL						
T5	DDR_BA_0	DDR	SSTL						
T17	SSIOEN1	GPIO	CMOS	ssi0_en1	norspi_en[1]				39
T18	SC_D0	GPIO	CMOS	sc_d0	uart2_ahb_rx	ssis_sclk		pwm_0	20
T19	SC_C0	GPIO	CMOS	sc_c0	uart2_ahb_rx	ssis_sclk			16
T20	SC_B0	GPIO	CMOS	sc_b0	ssi1_en1	norspi_dq[3]			12
T21	SC_A0	GPIO	CMOS	sc_a0	ssi1_sclk	norspi_clk	pwm_0		8
U1	DDR_DQ_8	DDR	SSTL						
U2	DDR_DQ_9	DDR	SSTL						
U3	DDR_DQ_1	DDR	SSTL						
U4	DDR_DQ_0	DDR	SSTL						
U5	DDR_BA_2	DDR	SSTL						
U6	CLK_SI	Sensor	CMOS						
U7	VD0_OUT_8	VOUT	CMOS	vd0_out[8]					126
U8	VD0_HSYNC	VOUT	CMOS	VD0_HSYNC					136
U9	ENET_MDC	ENET	CMOS	enet_mdc		enet_mdc			66
U10	ENET_CLK_RX	ENET	CMOS	enet_ref_clk		enet_clk_rx			69
U11	POR_I								
U12	I2S_CLK	I2S	CMOS	i2s_clk	dmic_clk				51
U13	JTAG_TDI	JTAG	CMOS						

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
U14	IDCDATA	IDC	CMOS	idc0data					29
U15	GPIO_4	GPIO	CMOS	ehci_prt_pwr_1	uart2_ahb_rts_n	ssis_en	sc_c3		4
U16	UART1CTSN	GPIO	CMOS	uart1_ahb_cts_n					49
U17	UART1RTSN	GPIO	CMOS	uart1_ahb_rts_n					50
U18	SC_D1	GPIO	CMOS	sc_d1	uart2_ahb_tx	ssis_rxd		pwm_1	21
U19	SC_C1	GPIO	CMOS	sc_c1	uart2_ahb_tx	ssis_rxd			17
U20	SC_B1	GPIO	CMOS	sc_b1	ssi1_en2	norspi_en[0]	norspi_dq[2]		13
U21	SC_A1	GPIO	CMOS	sc_a1	ssi1_txd	norspi_dq[0]	pwm_1		9
V1	VD0_OUT_14	VOUT	CMOS	vd0_out[14]					132
V2	VD0_OUT_15	VOUT	CMOS	vd0_out[15]					133
V3	VD0_OUT_10	VOUT	CMOS	vd0_out[10]					128
V4	VD0_CLK	VOUT	CMOS	vd0_clk					134
V5	DDR RESET	DDR	SSTL						
V6	CLK_SI2	Sensor	CMOS						
V7	VD0_OUT_7	VOUT	CMOS	vd0_out[7]					125
V8	ENET_MDIO	ENET	CMOS	enet_mdio		enet_mdio			67
V9	ENET_CLK_TX	ENET	CMOS	enet_2nd_ref_clk		enet_clk_tx			68
V10	TEST_MODE	GLOBAL	CMOS						
V11	I2S_SI	GPIO	CMOS	i2s_si	dmic_dat				52
V12	JTAG_TMS	JTAG	CMOS						
V13	IDC2CLK	IDC	CMOS	idc1clk		norspi_dq[2]	norspi_en[2]		30
V14	GPIO_5	GPIO	CMOS	pwm_1	idsp_pip_iopad_master_hsync	vin_strig0	sc_d0	uart2_ahb_cts_n	5
V15	GPIO_0	GPIO	CMOS	sd_hs_sel					0
V16	GPIO_1	GPIO	CMOS	ehci_app_prt_ovcurr0	uart2_ahb_rx	ssis_sclk	sc_c0		1
V17	SC_D2	GPIO	CMOS	sc_d2	uart2_ahb_cts_n	ssis_txd		pwm_2	22
V18	SC_D3	GPIO	CMOS	sc_d3	uart2_ahb_rts_n	ssis_en		pwm_3	23
V19	SC_C2	GPIO	CMOS	sc_c2	uart2_ahb_cts_n	ssis_txd			18
V20	SC_B2	GPIO	CMOS	sc_b2	ssi1_en3	norspi_en[1]	norspi_dq[3]		14
V21	SC_A2	GPIO	CMOS	sc_a2	ssi1_rxd	norspi_dq[1]	pwm_2		10
W1	VD0_OUT_4	VOUT	CMOS	vd0_out[4]					122

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
W2	VD0_OUT_6	VOUT	CMOS	vd0_out[6]					124
W3	VD0_OUT_1	VOUT	CMOS	vd0_out[1]					119
W4	VD0_OUT_11	VOUT	CMOS	vd0_out[11]					129
W5	DDR_VREF_1	DDR	SSTL						
W6	VD0_OUT_0	VOUT	CMOS	vd0_out[0]					118
W7	VD0_HVLD	VOUT	CMOS	vd0_hvld					137
W8	ENET_TXD_0	ENET	CMOS	enet_txd_0	sc_a1	enet_txd_0	ssi1_en0	norspi_en[1]	57
W9	ENET_TXEN	ENET	CMOS	enet_txen	sc_a0	enet_txen	ssi1_txd	norspi_en[0]	56
W10	ENET_RXD_2	ENET	CMOS		sc_b3	enet_rxd_2		norspi_dq[2]	63
W11	ENET_RXD_3	ENET	CMOS			enet_rxd_3		norspi_dq[3]	64
W12	I2S_SO	I2C	CMOS	i2s_so					53
W13	JTAG_CLK	JTAG	CMOS						
W14	IDC2DATA	IDC	CMOS	idc1data		norspi_dq[3]	norspi_en[3]		31
W15	GPIO_6	GPIO	CMOS	pwm_2	idsp_pip_iopad_master_vsync	vin_strig1	sc_d1	uart2_ahb_rts_n	6
W16	GPIO_2	GPIO	CMOS	ehci_app_prt_ovcurr1	uart2_ahb_tx	ssis_rxd	sc_c1		2
W17	UART1RX	GPIO	CMOS	uart1_ahb_rx					47
W18	TIMER1	GPIO	CMOS	tm12_clk	ssi2_en3	idsp_pip_iopad_master_hysnc			26
W19	SC_C3	GPIO	CMOS	sc_c3	uart2_ahb_rts_n	ssis_en			19
W20	SC_B3	GPIO	CMOS	sc_b3	pwm_3	norspi_en[2]			15
W21	SC_A3	GPIO	CMOS	sc_a3	ssi1_en0	norspi_dq[2]	pwm_3		11
Y1	SSI2EN1	GPIO	CMOS	ssi2_en1					44
Y2	SSI2MISO	GPIO	CMOS	ssi2_rxd					42
Y3	VD0_OUT_5	VOUT	CMOS	vd0_out[5]					123
Y4	VD_PWM	VOUT	CMOS	pwm_0					138
Y5	VD0_OUT_2	VOUT	CMOS	vd0_out[2]					120
Y6	VD0_OUT_12	VOUT	CMOS	vdo_out[12]					130
Y7	VD0_VSYNC	VOUT	CMOS	vd0_vsync					135
Y8	ENET_TXD_1	ENET	CMOS	enet_txd_1	sc_a2	enet_txd_1	ssi1_en1	norspi_en[2]	58
Y9	ENET_GTX_CLK	ENET	CMOS	enet_gtx_clk		enet_gtx_clk	ssi1_sclk	norspi_clk	70
Y10	ENET_RXD_1	ENET	CMOS	enet_rxd_1	sc_b2	enet_rxd_1		norspi_dq[1]	62

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
Y11	ENET_RXDV	ENET	CMOS	enet_rxdv		enet_rxdv			65
Y12	I2S_WS	I2C	CMOS	i2s_ws					54
Y13	JTAG_TDO	JTAG	CMOS						
Y14	IDC3CLK	IDC	CMOS	idc2clk	vin_strig0				32
Y15	GPIO_7	GPIO	CMOS	sdxc_hs_sel					7
Y16	GPIO_3	GPIO	CMOS	ehci_prt_pwr_0	uart2_ahb_cts_n	ssis_txd	sc_c2		3
Y17	UART1TX	GPIO	CMOS	uart1_ahb_tx					48
Y18	SSIOMISO	GPIO	CMOS	ssi0_rxd	norspi_dq[1]	uart2_ahb_cts_n	ssis_txd		
Y19	FSOURCE_0	GLOBAL	Supply / GND						
Y20	VDDWL_0	POWER	IO POWER						
Y21	SC_E0	GPIO	CMOS	sc_e0	ssi0_en2	norspi_en[3]		pwm_1	24
AA1	SSI2EN0	GPIO	CMOS	ssi2_en0					43
AA2	SSI2MOSI	GPIO	CMOS	ssi2_txd	idc3data				41
AA3	SENSOR_RST	GPIO	CMOS						117
AA4	SSI2CLK	GPIO	CMOS	ssi2_sclk	idc3clk				40
AA5	VD0_OUT_3	VOUT	CMOS	vd0_out[3]					121
AA6	VD0_OUT_13	VOUT	CMOS	vd0_out[13]					131
AA7	VD0_OUT_9	VOUT	CMOS	vd0_out[9]					127
AA8	ENET_TXD_2	ENET	CMOS		sc_a3	enet_txd_2	ssi1_en2		59
AA9	ENET_TXD_3	ENET	CMOS		sc_b0	enet_txd_3	ssi1_en3		60
AA10	ENET_RXD_0	ENET	CMOS	enet_rxd_0	sc_b1	enet_rxd_0	ssi1_rxd	norspi_dq[0]	61
AA11	ENET_EXT_OSC_CLK	ENET	CMOS			enet_ext_osc_clk			71
AA12	CLK_AU	GPIO	CMOS	clk_au	clk_au3				55
AA13	JTAG_RST_I	JTAG	CMOS						
AA14	IDC3DATA	IDC	CMOS	idc2data	vin_strig1				
AA15	IDCCLK	IDC	CMOS	idc0clk					28
AA16	UART0TX	GPIO	CMOS	uart0tx	uart2_ahb_tx				46
AA17	UART0RX	GPIO	CMOS	uart0rx	uart2_ahb_rx				45
AA18	SSIOMOSI	GPIO	CMOS	ssi0_txd	norspi_dq[0]	uart2_ahb_tx	ssis_rxd		36
AA19	SSIOCLK	GPIO	CMOS	ssi0_sclk	norspi_clk	uart2_ahb_rx	ssis_sclk		35
AA20	TIMER2	GPIO	CMOS	tm13_clk	ssi0_en3	IDSP_PIP_IOPAD_MASTER_VSYNC			27

Loc.	Pin Name	Group	Type	Multiplexed Functions					
				First	Second	Third	Fourth	Fifth	GPIO
AA21	TIMER0	GPIO	CMOS	tm11_clk	ssi2_en2				25

Table 7-1. Pin List and Mapping Table for the H22S75 Chip.

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8. TYPOGRAPHICAL CONVENTIONS

This document provides technical detail using a set of consistent typographical conventions to help the user differentiate key concepts at a glance. Conventions include:

Example	Description
AmbaGuiGen, DirectUSB Save, File > Save Power, Reset, Home	Software names GUI commands and command sequences Computer / Hardware buttons
Flash_IO_control da, status, enable	Register names and register fields. For example, Flash_IO_control is the register for global control of Flash I/O, and bit 17 (da) is used for DMA acknowledgement.
GPIO81, CLK_AU	Hardware external pins
VIL, VIH, VOL, VOH	Hardware pin parameters
INT_O, RXDATA_I	Hardware pin signals
amb_performance_t amb_operating_mode_t amb_set_operating_mode()	API details (e.g., functions, structures, and type definitions)
/usr/local/bin success = amb_set_operating_ mode (amb_xx_base_address, & operating_mode)	User entries into software dialogues and GUI windows File names and paths Command line scripting and Code

Table 8-1. *Typographical Conventions for Technical Documents.*

Additional Ambarella typographical conventions include:

- Acronyms are given in UPPER CASE using the default font (e.g., AHB, ARM11 and DDRIO).
- Names of Ambarella documents and publicly available standards, specifications, and databooks appear in *italic* type.

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10. REVISION HISTORY

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NOTE: Page/chapter numbers for previous drafts may differ from those in the current version.

Version	Date	Comments
0.1	7 February, 2017	Initial draft
0.2	15 March 2017	Updated Section 2.12: UART Interface, Section 1.2: Feature List, and Figure 1-1: H22S75 Overview to reflect three UARTs instead of two Deleted IVDDA spec in Section 4.3.7.1 DC Spec Updated FCLK spec in Section 4.3.7.2 AC Spec Updated Pin P8 from VSSI to VDDP and D9 from VDDP to VSSI per latest pin map in Chapters 3 and 7 Added Chapter 4: Electrical
0.3	2 August 2017	Updated Table 2-6: SSI / SPI Master with Device Enable Detail Fixed typos and updated ADC to three channels in Chapter 1 and 2 Updated Core Voltage to 0.85V

Table 10-1. Revision History.